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Flexible Cell Interconnection Using Al-Foils and Laser Processing

Our Services for the Industry

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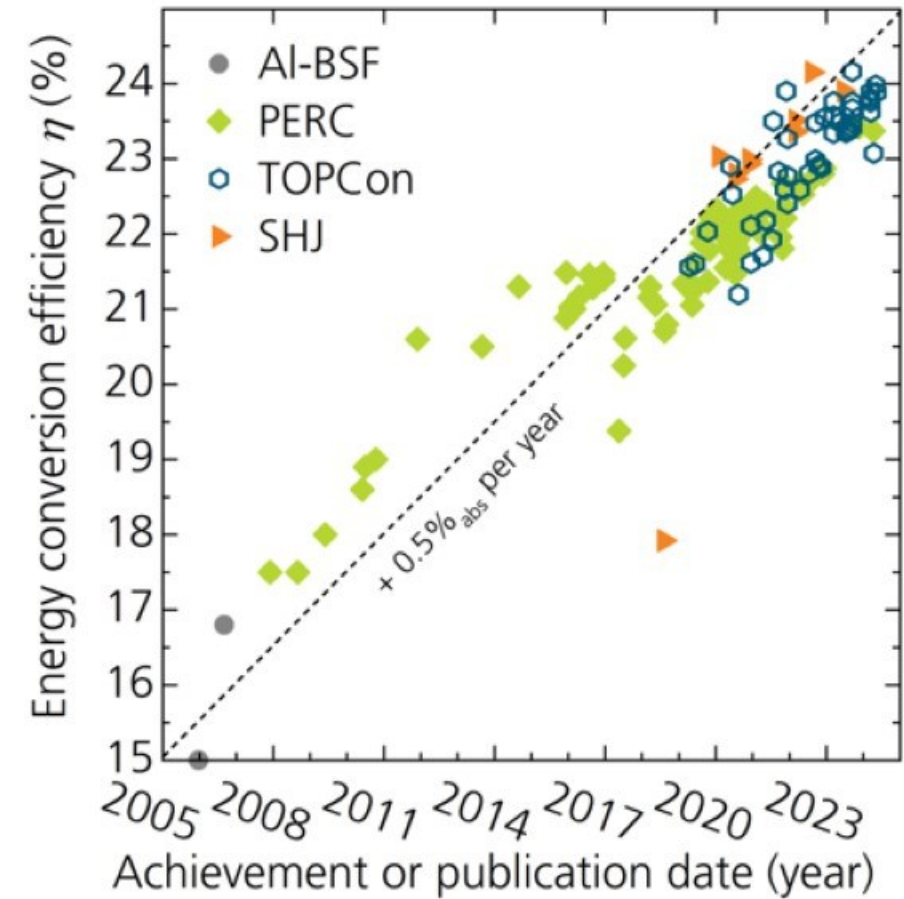


Accredited Laboratories



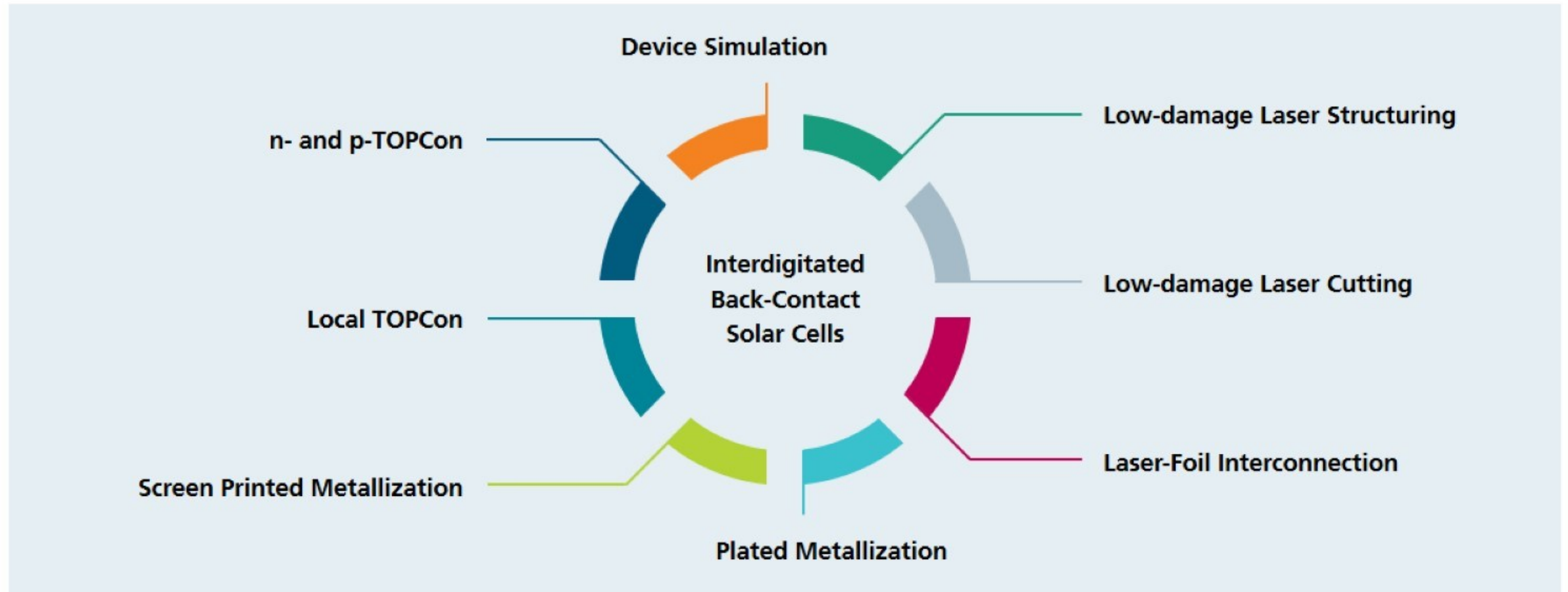
Fraunhofer ISE - Photovoltaic Technology Evaluation Center (PV-TEC)

Pilot-line Production of Mainstream Industrial Solar Cells



Processes Relevant for Back-Contact Cells at Fraunhofer ISE

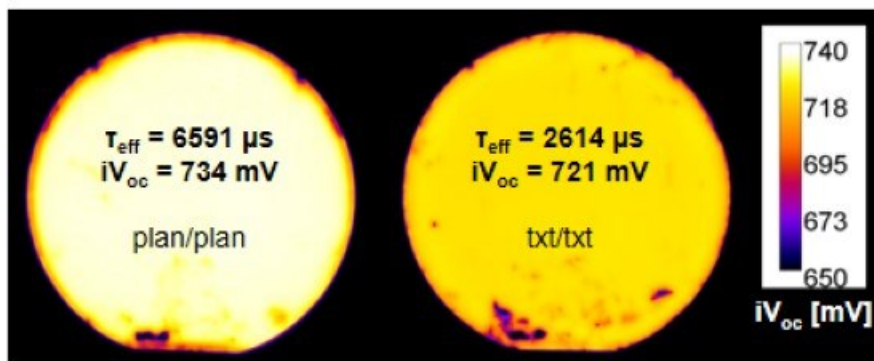
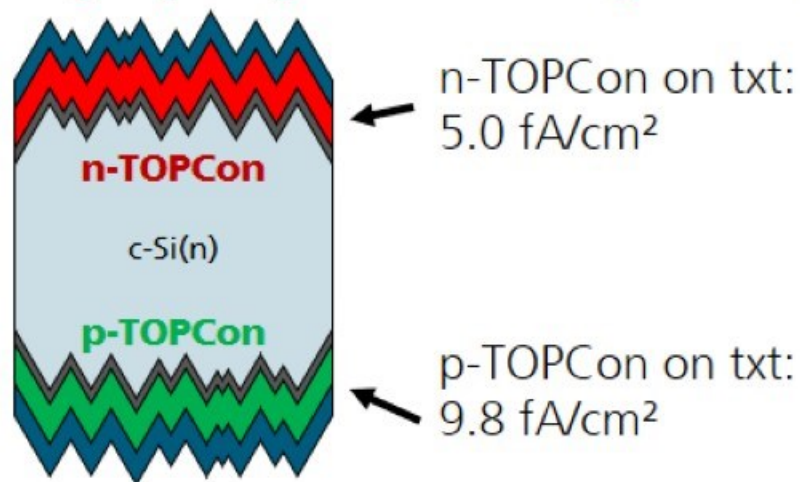
Passivation, Structuring, Metallization and Interconnection



Processes Relevant for Back-Contact Cells at Fraunhofer ISE

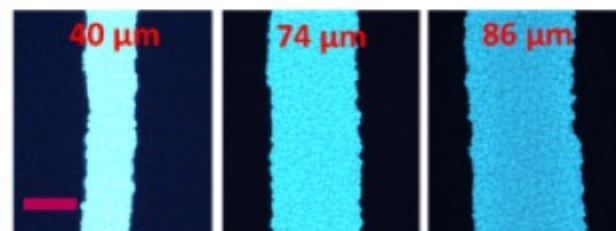
TOPCon Passivation and Local TOPCon

High-quality Passivation by PECVD p-TOPCon ^{1, 2}

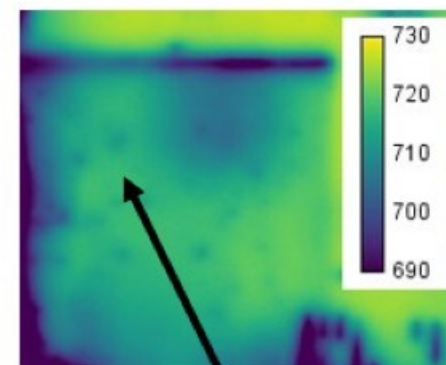


Local p-TOPCon by Dopant Ink Printing ^{3, 4}

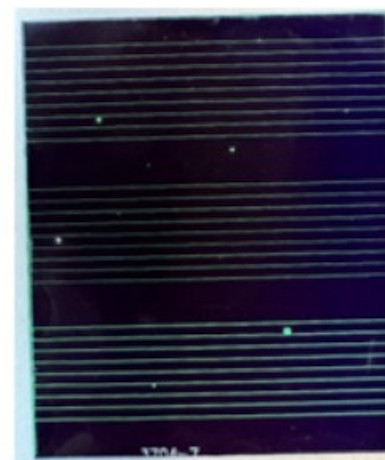
Printed dopant ink lines



PL of Local TOPCon



Local p-TOPCon
 $\sim 716 \text{ mV}$

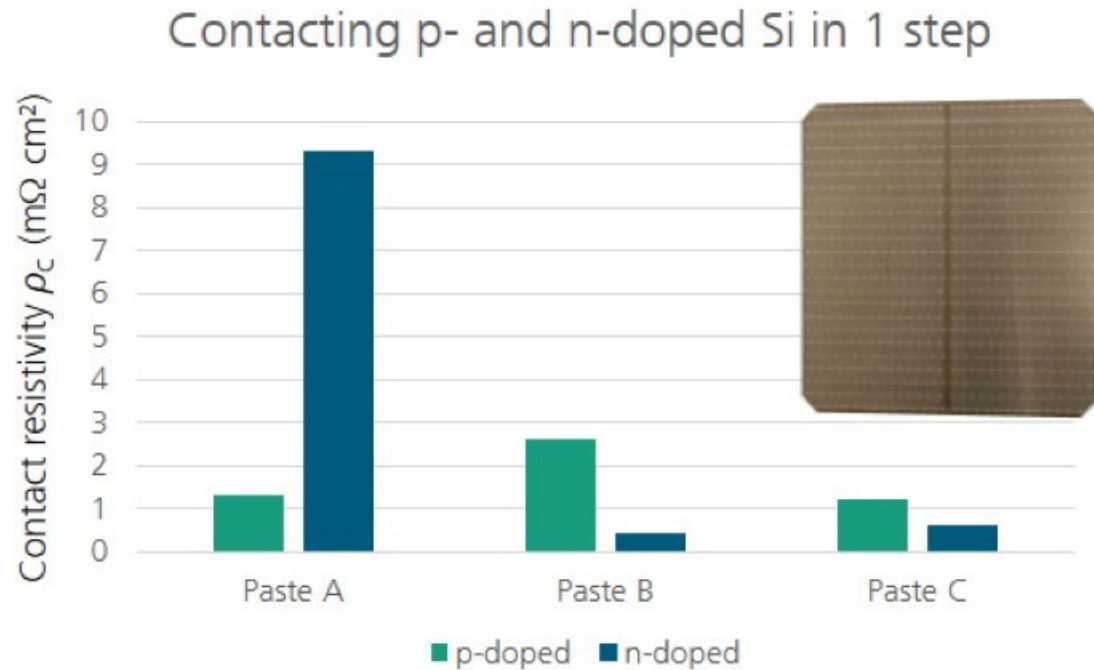


Local p-TOPCon
lines after etching

Processes Relevant for Back-Contact Cells at Fraunhofer ISE

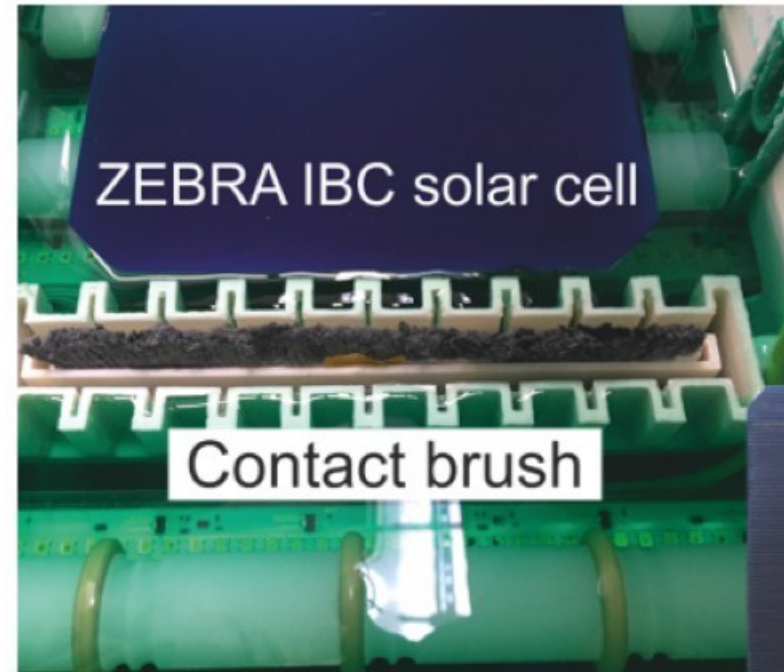
Screen Printed and Plated Metallization

Screen printed Metallization for IBC^{1, 2}



Analysis of unipolar metallization using a single screen printing step

Mask-less Plating for IBC^{3, 4}



Adjusted plating setup for single-side contacting and mask-less plating

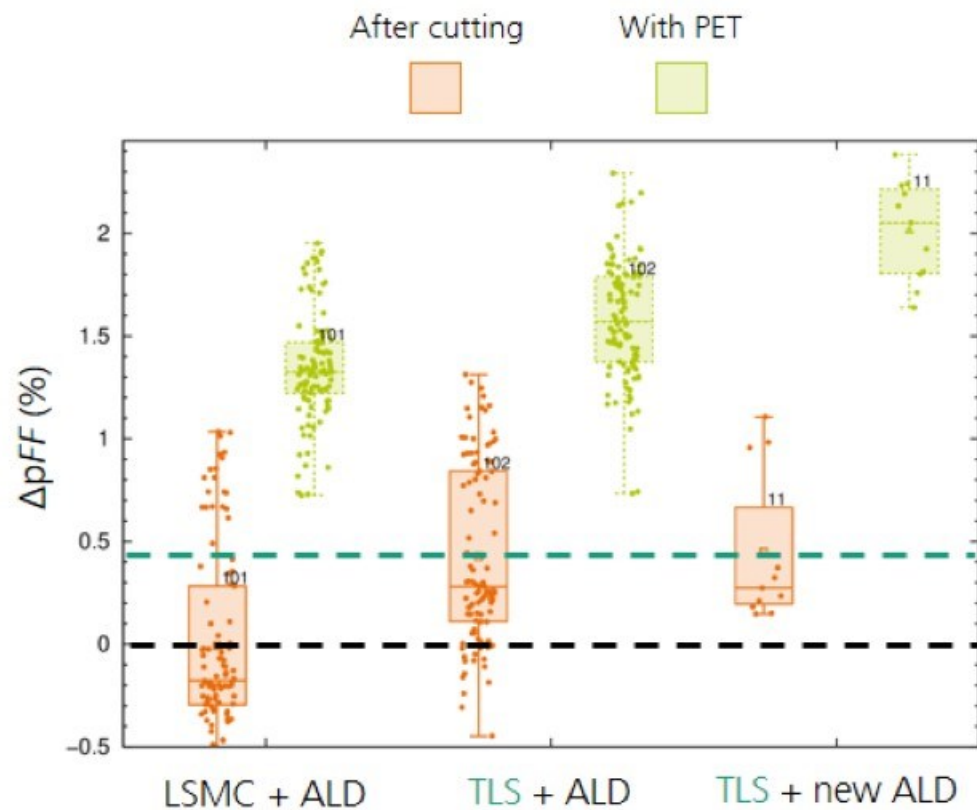
M2-size ZEBRA-IBC with plated Cu-metallization



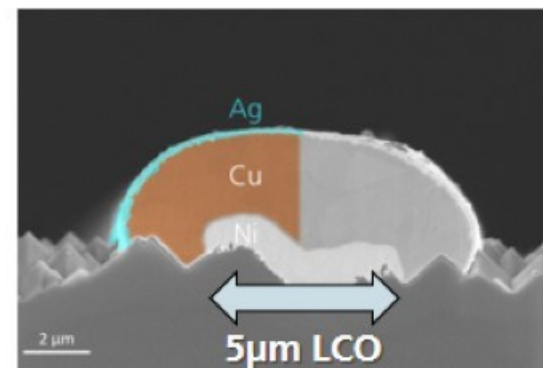
Processes Relevant for Back-Contact Cells at Fraunhofer ISE

Low-damage Cutting and Laser Structuring

Low-damage Cutting and Edge Passivation ^{1, 2}

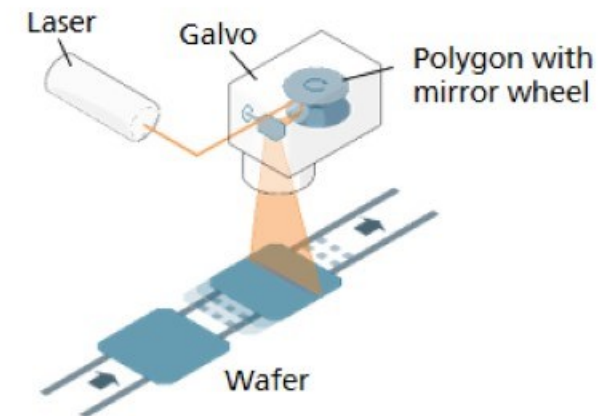


Low-damage Laser Structuring ^{3, 4}



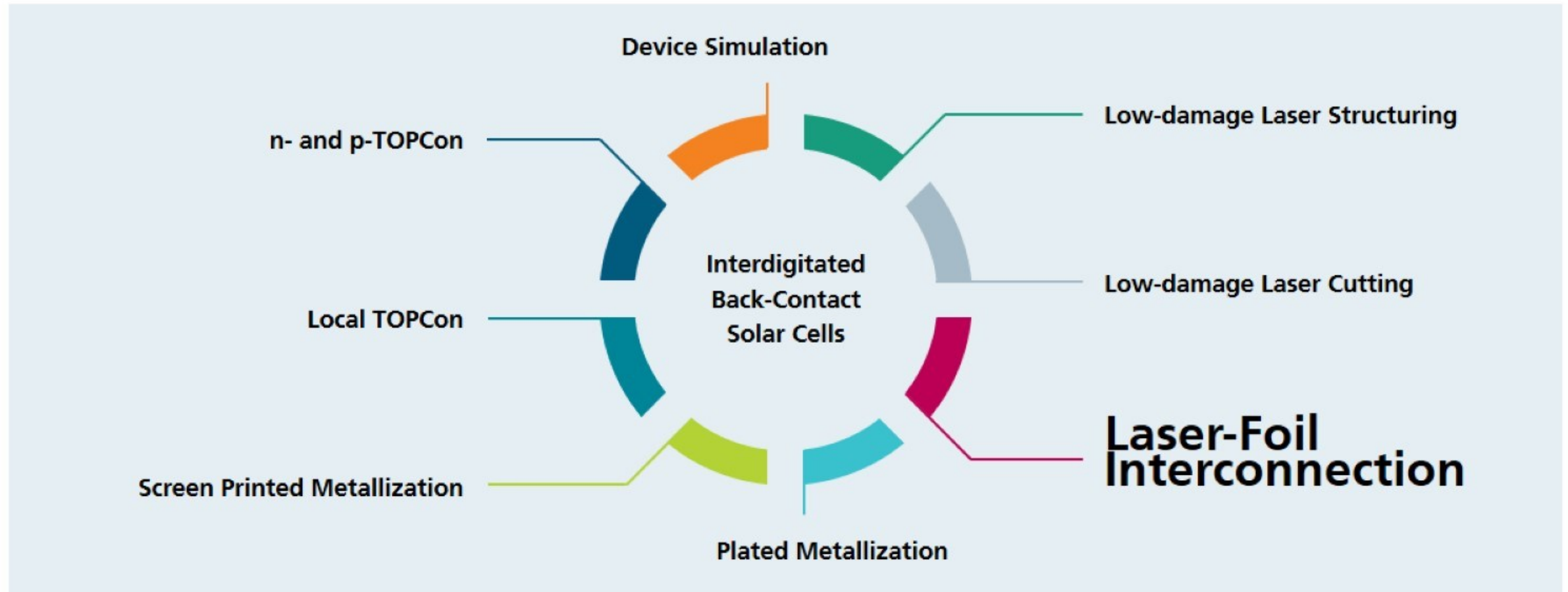
Super small ...
($< 10 \mu m$)

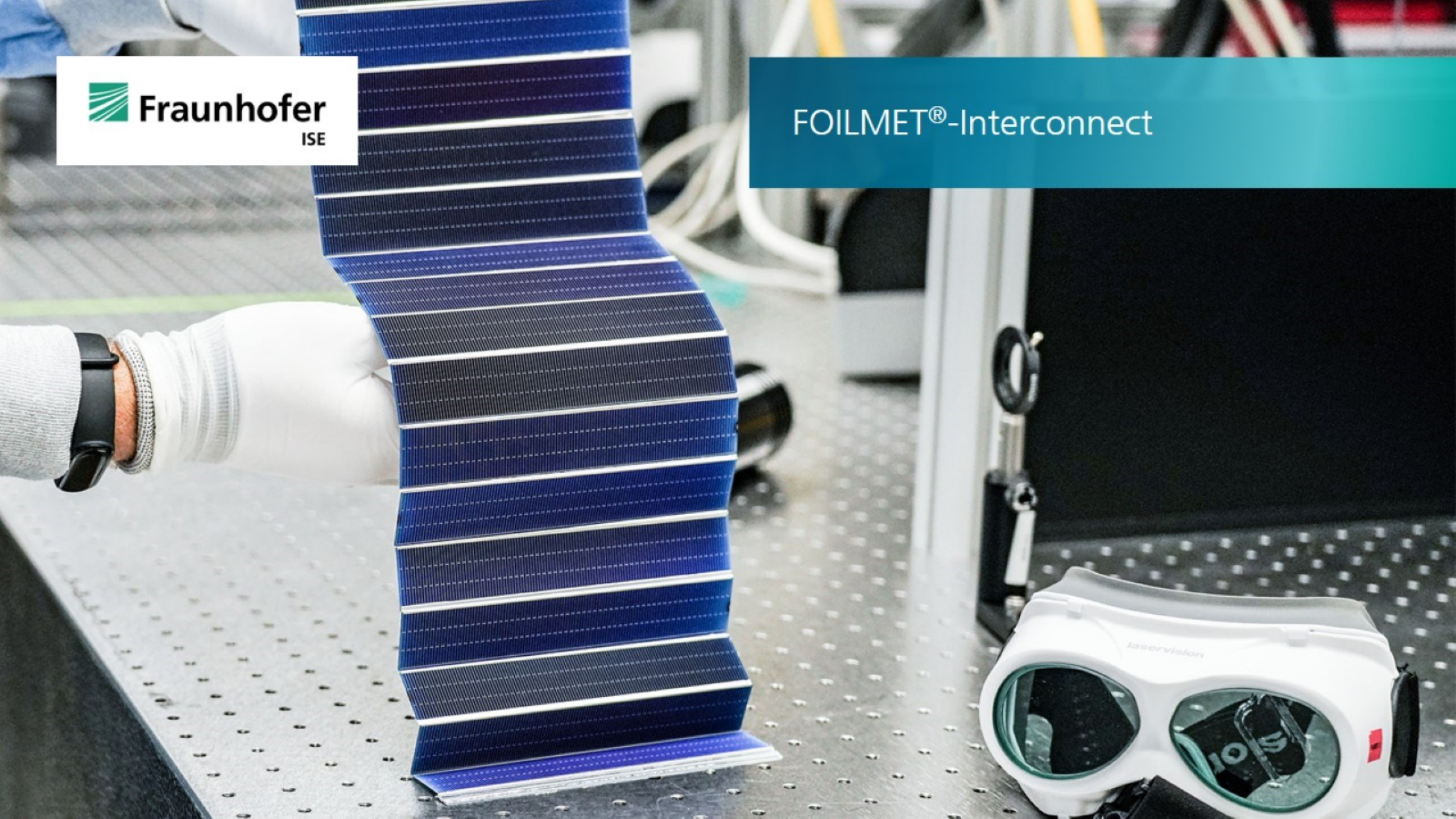
... and super fast
($> 5,000,000 / s$
„on the fly“)



Processes Relevant for Back-Contact Cells at Fraunhofer ISE

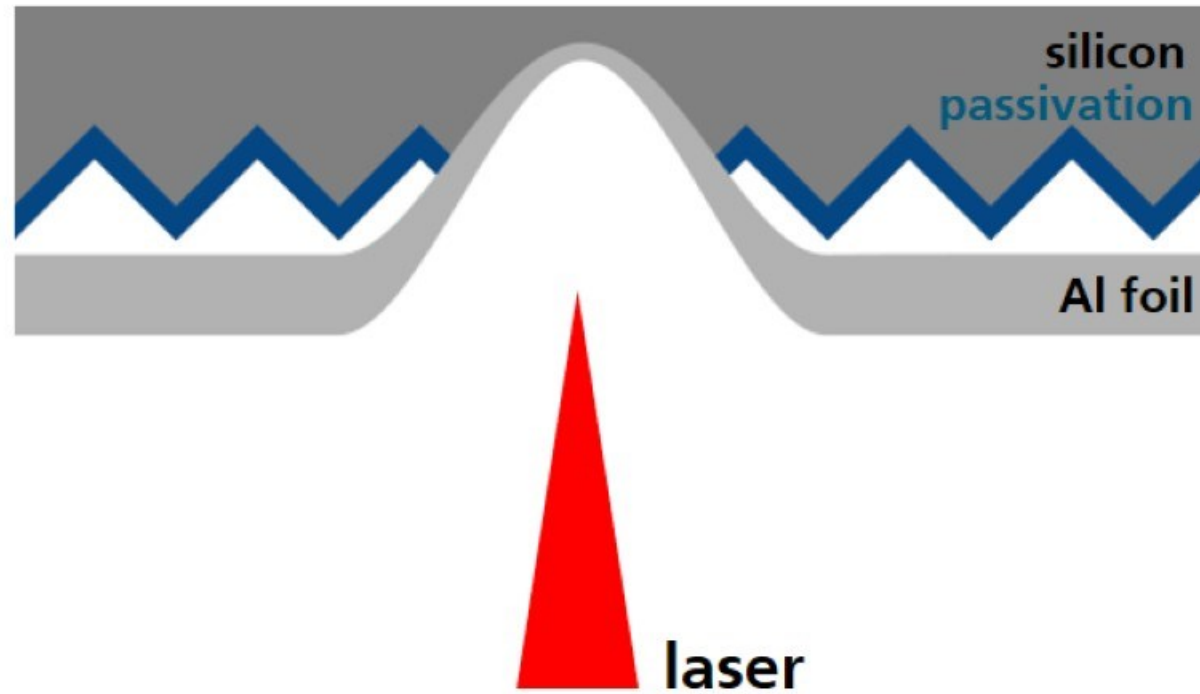
Passivation, Structuring, Metallization and Interconnection





Laser Joining Processes for Aluminum Foil

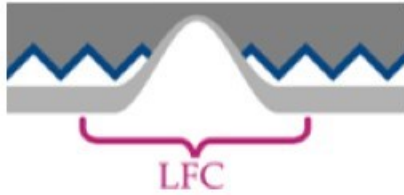
Laser Fired Contacts (LFC)



[2], [3]

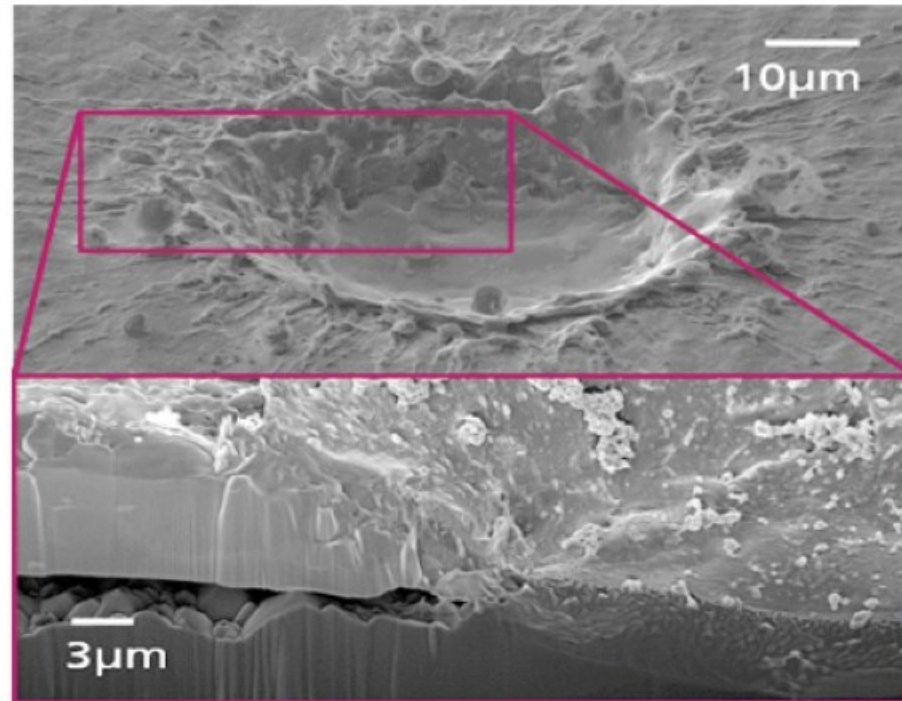
Laser Joining Processes for Aluminum Foil

Laser Fired Contacts (LFC)



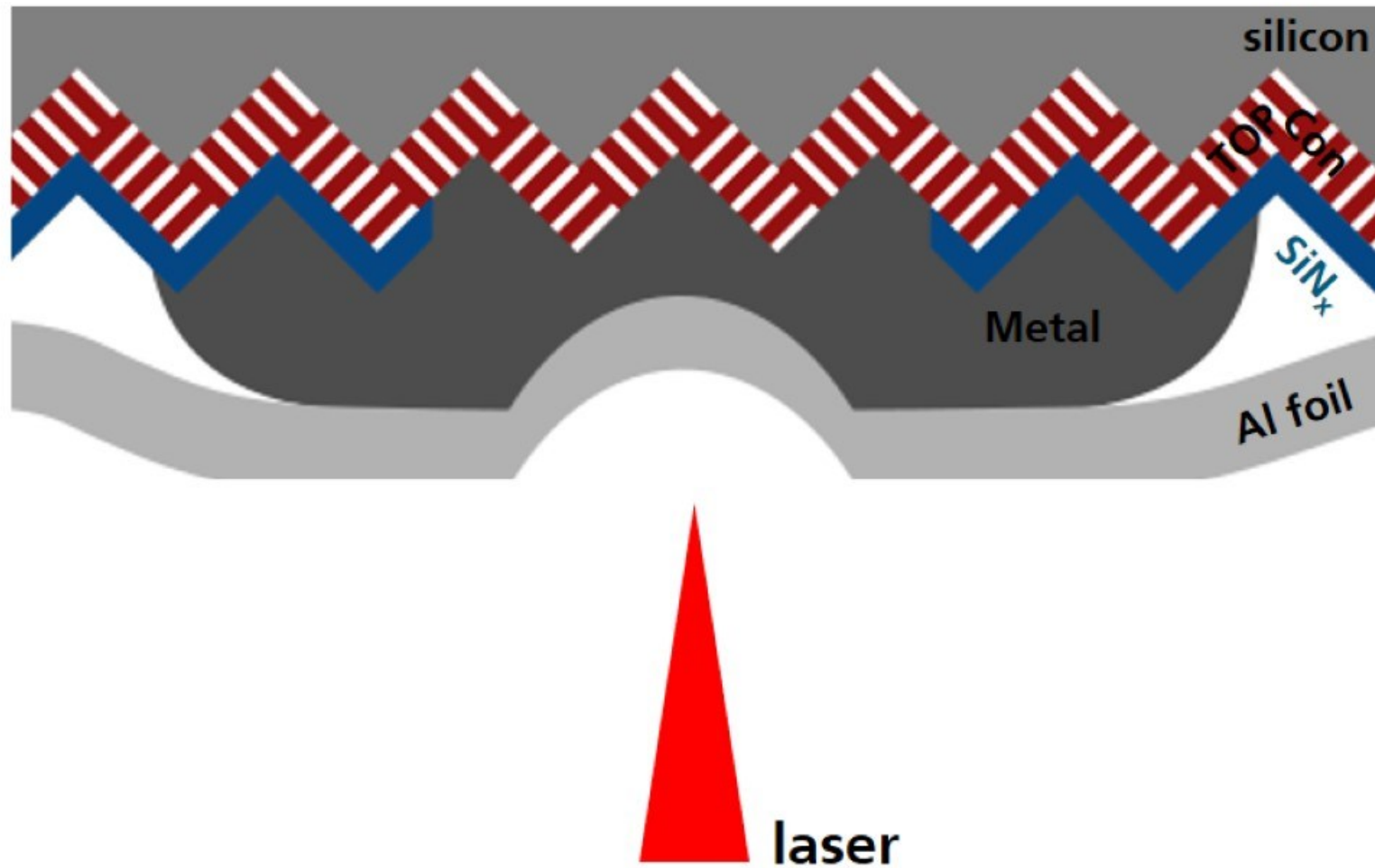
Properties of LFC

- Good electrical performance
- Good module stability
- Okay mechanical adhesion
- High **negative** impact on V_{oc}



Laser Joining Processes for Aluminum Foil

Laser Metal Welding (LMW)



[4], [5]

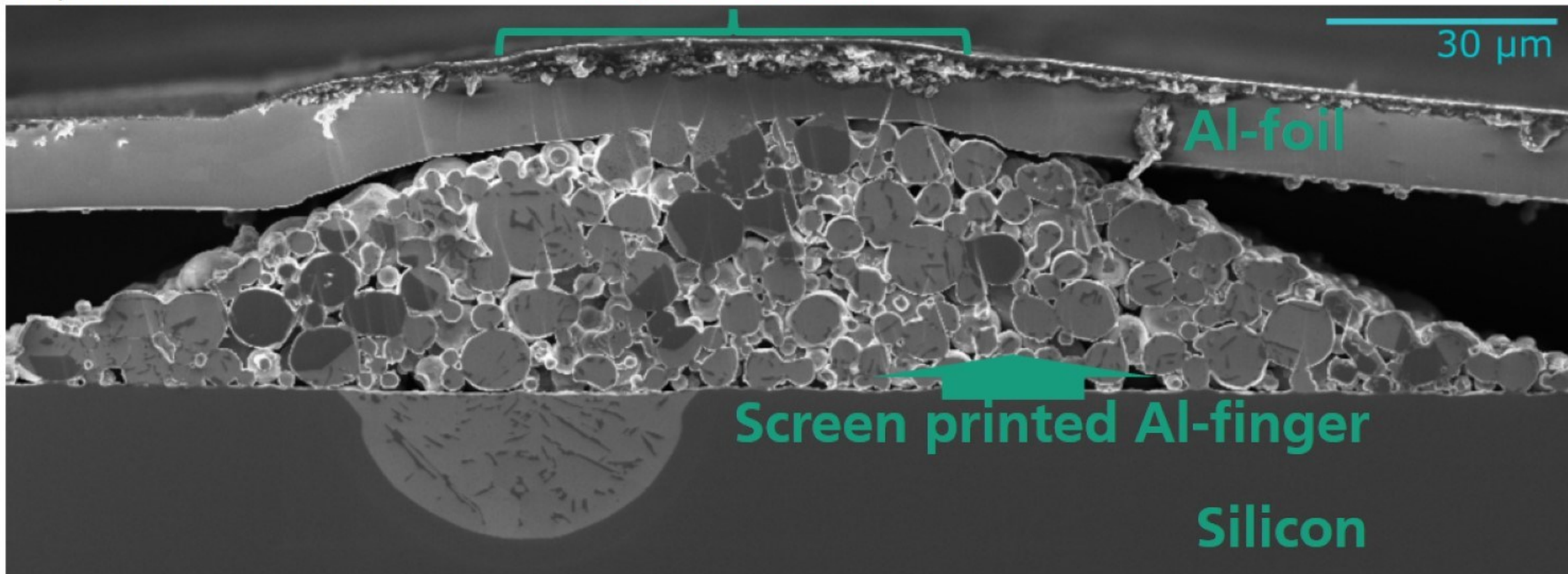
Investigation of Welding Sites

Al-Al Weld

Ion polished cross-section [2]

Laser weld

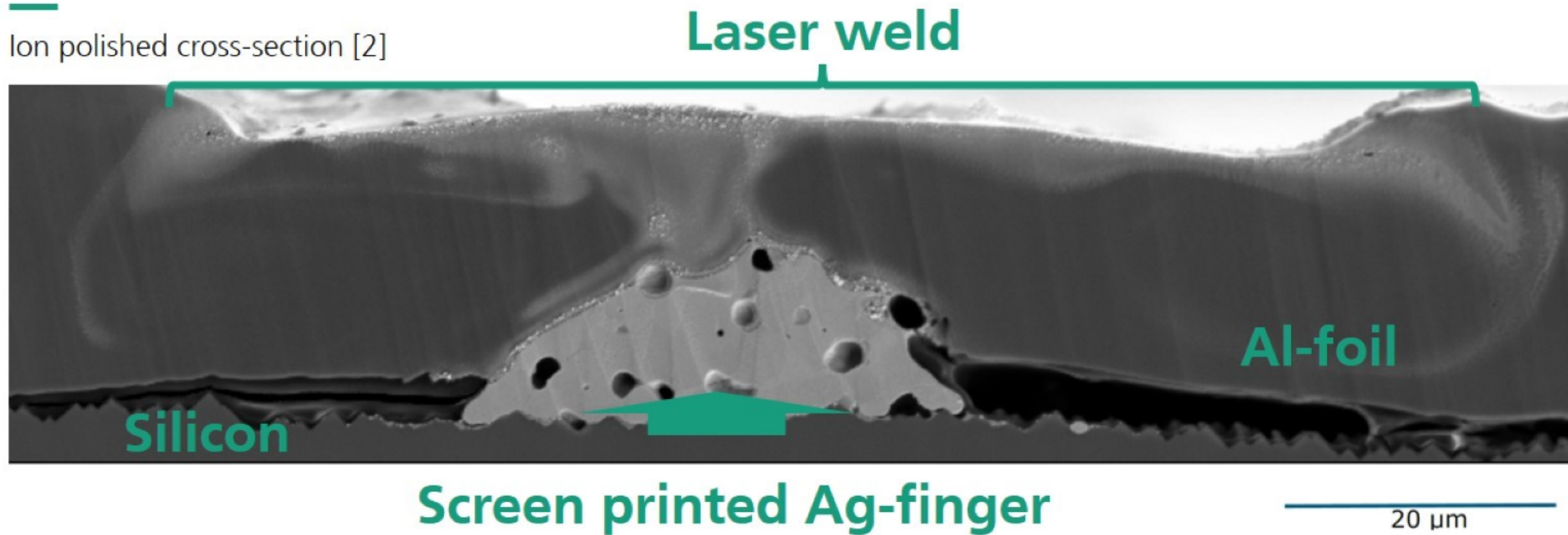
30 μm



Investigation of Welding Sites

Al-Ag Weld

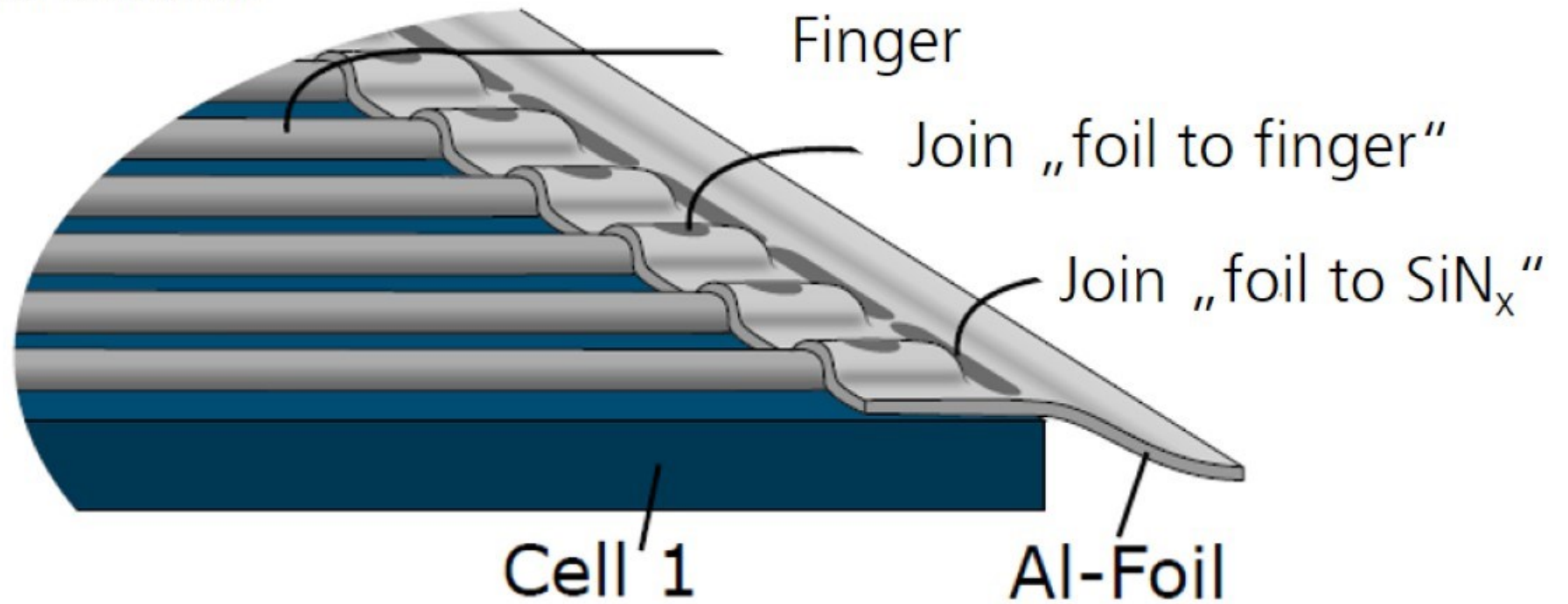
Ion polished cross-section [2]



Introduction "FOILMET[®]-Interconnect"

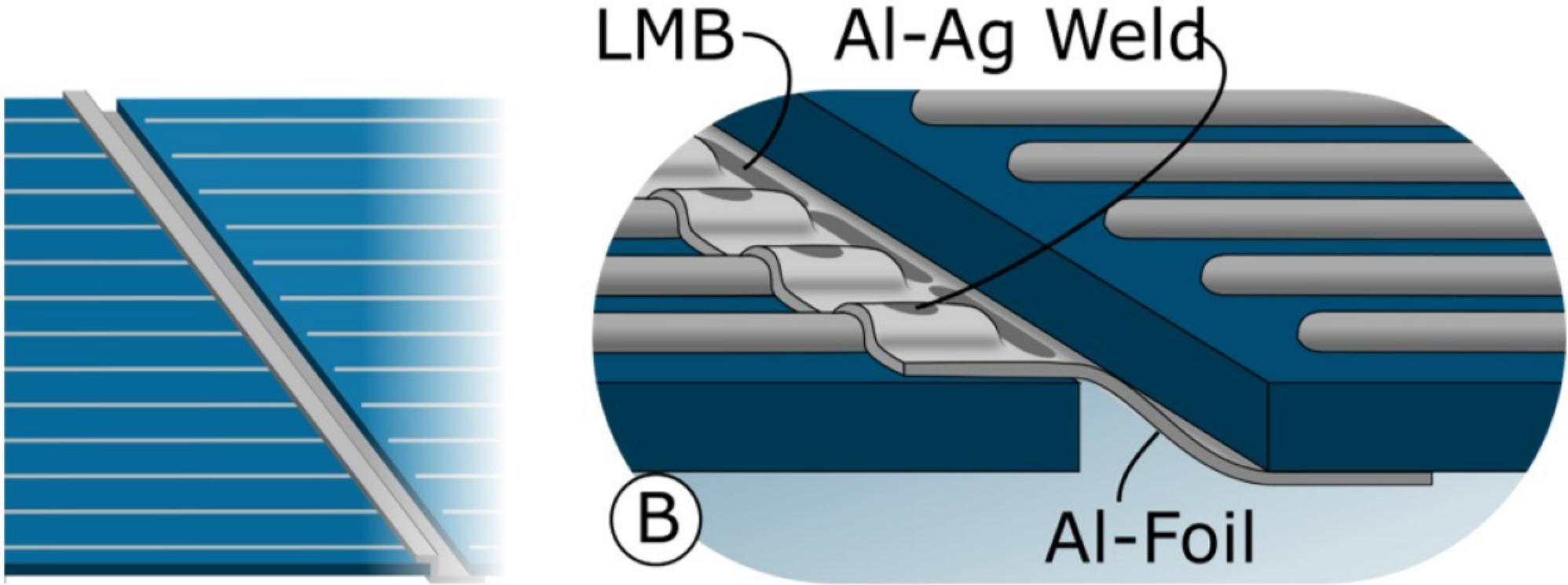
Principle

- Edge-interconnection → cut cell
- Aluminum foil (~ 10 μm)
- Laser joining → mechanical & electrical contacts



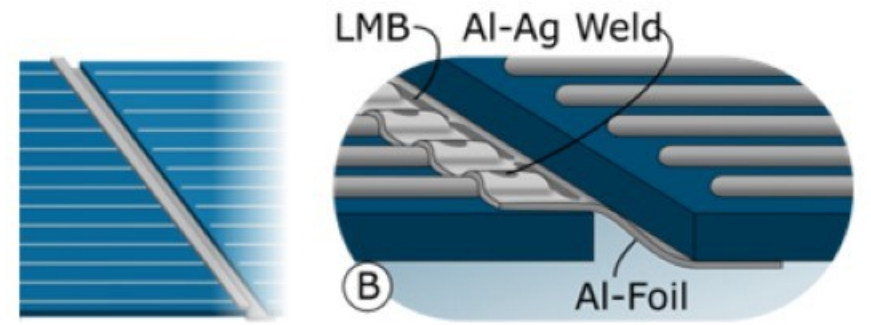
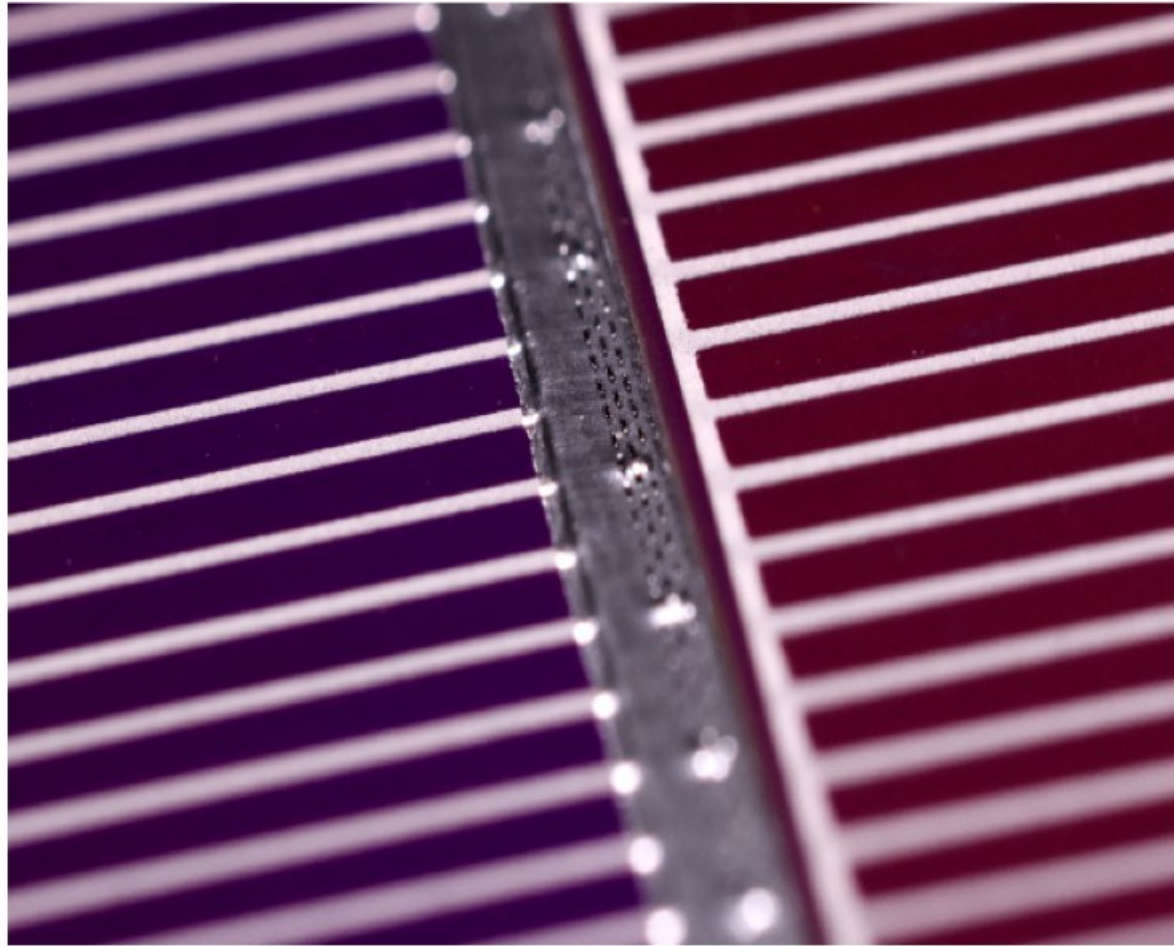
Introduction "FOILMET[®]-Interconnect"

Applications



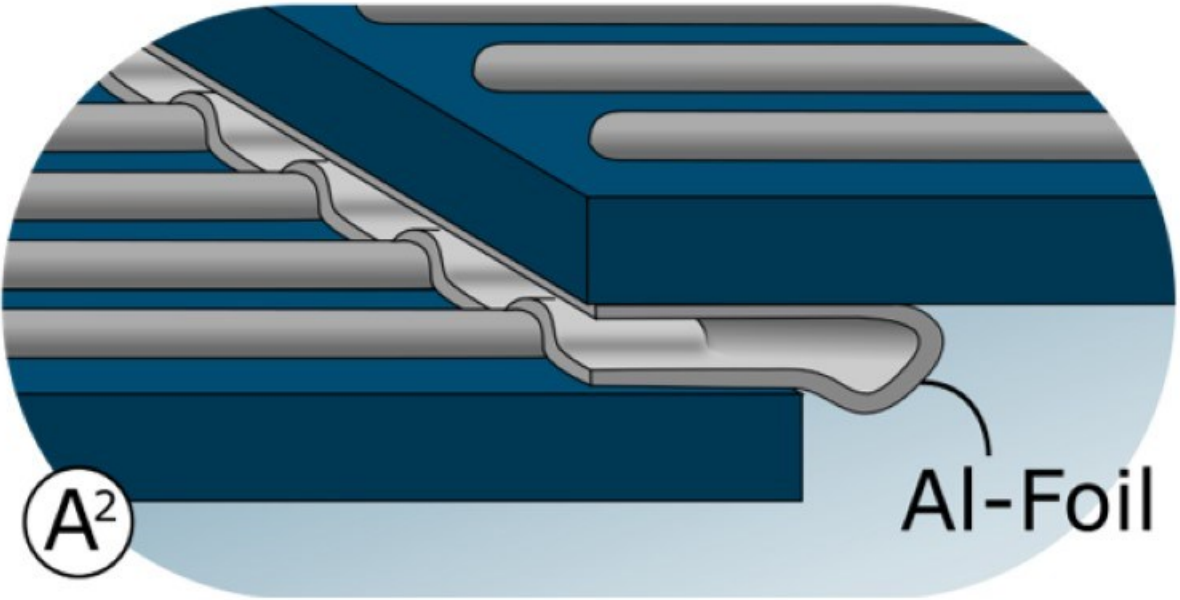
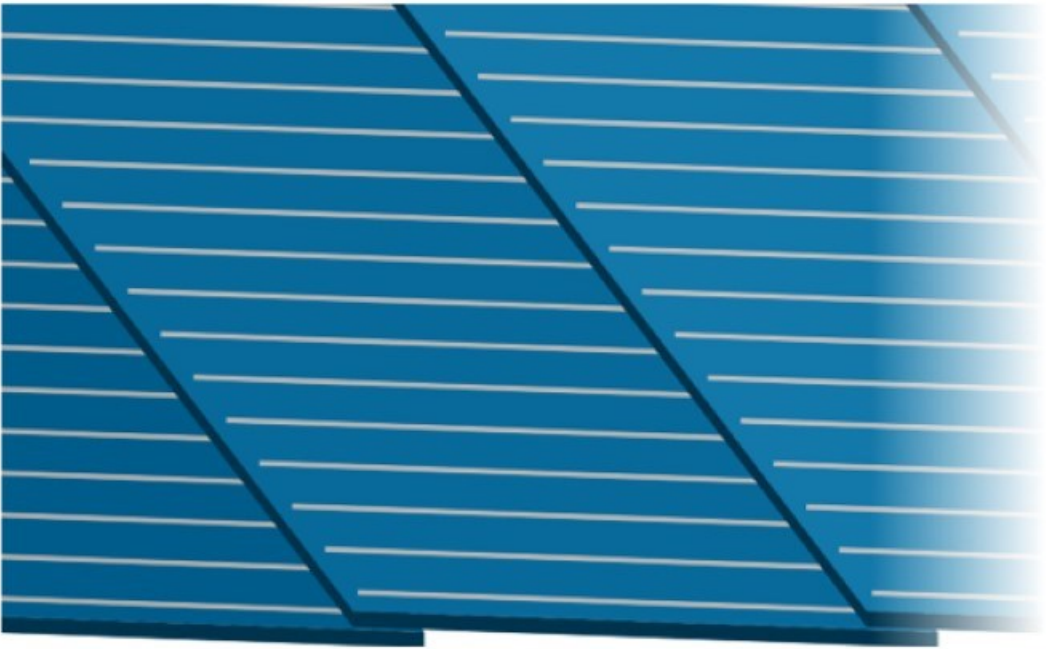
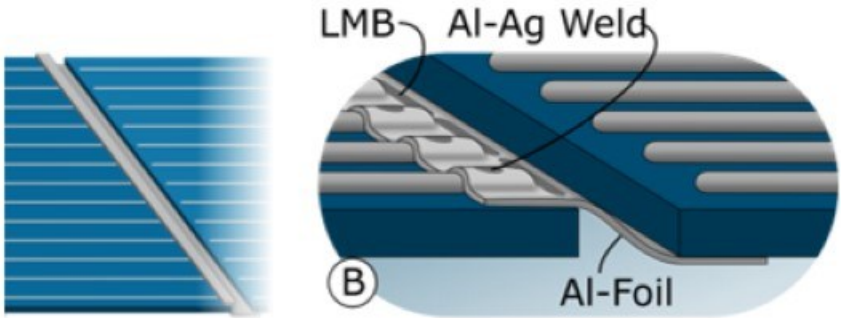
Introduction "FOILMET[®]-Interconnect"

Example



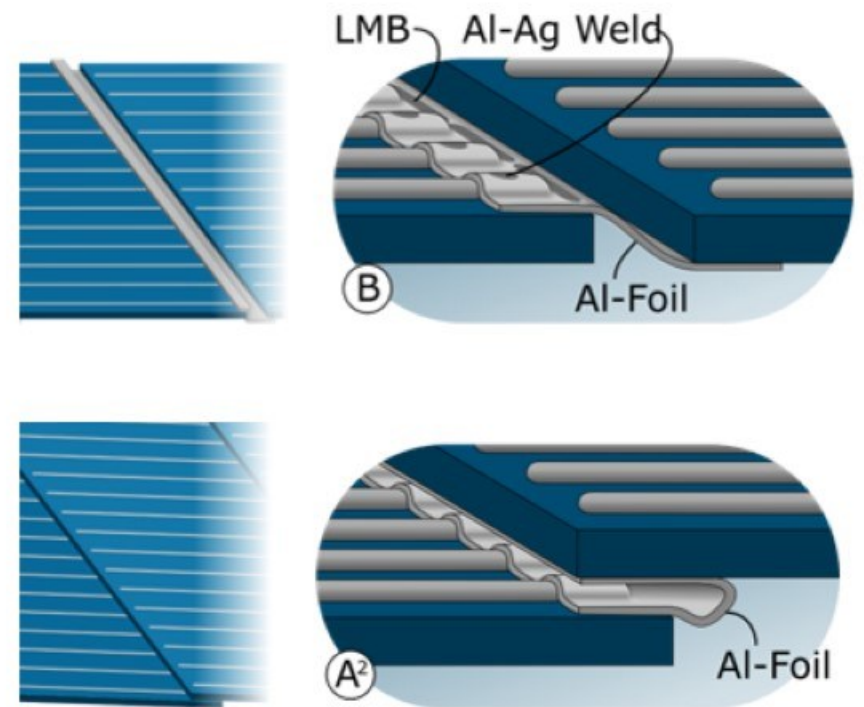
Introduction "FOILMET[®]-Interconnect"

Combination with Shingling



Introduction "FOILMET[®]-Interconnect"

Shingling Example



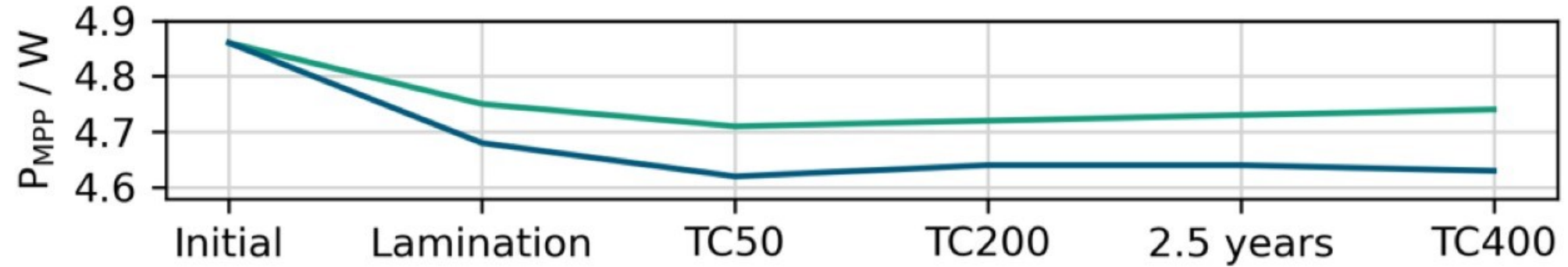
Introduction "FOILMET®-Interconnect"

Practical Adhesion Test

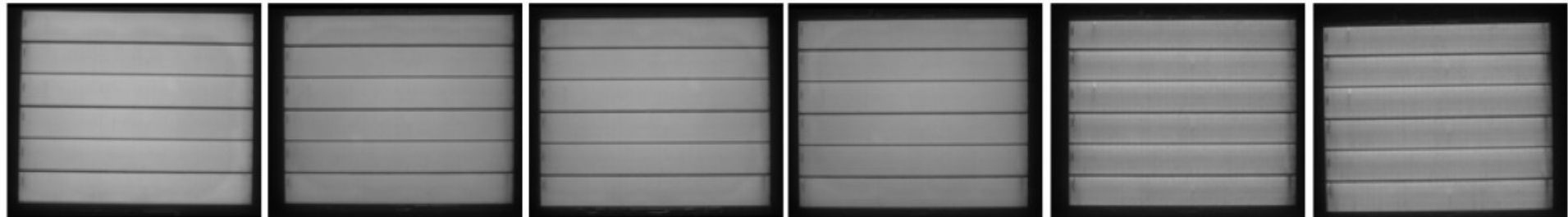


Temperature Cycle Results

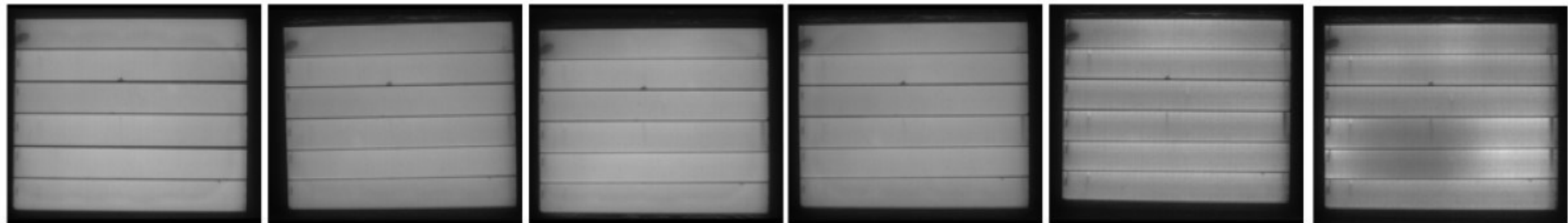
Electroluminescence (EL) and Peak Power P_{mpp}



String 1



String 2



[1] Paschen et al. PIP, 2021.

FoilMet meets MWT

FoilMet meets MWT – High Voltages by Simplified Series Interconnection

Screen Print Layout

Front

- Finger
- Busbar
- Via

Rear

- Finger
- Via

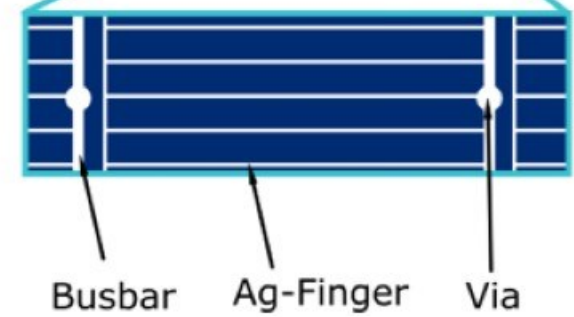
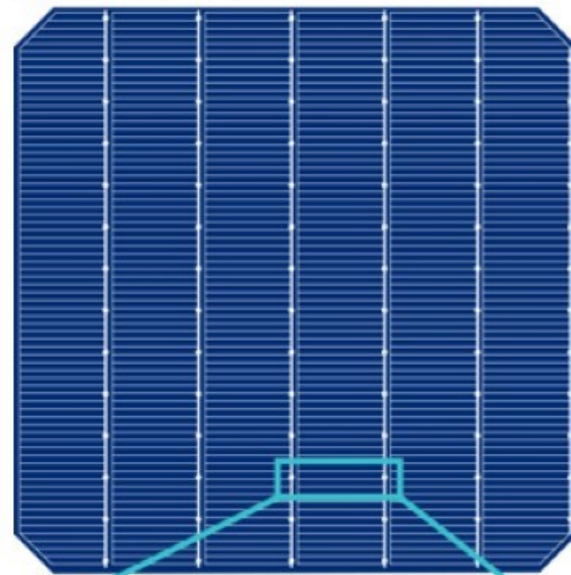
Al-Folie

- LMB on p-electrode
- LMB on n-electrode
- Cut foil

TLS cell

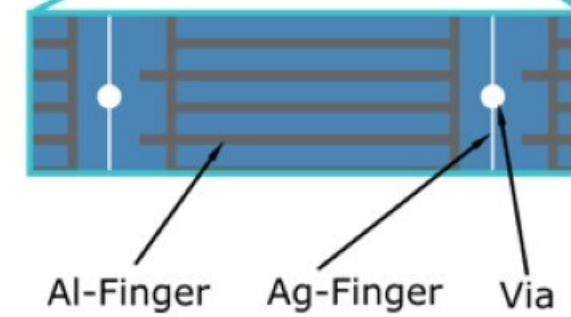
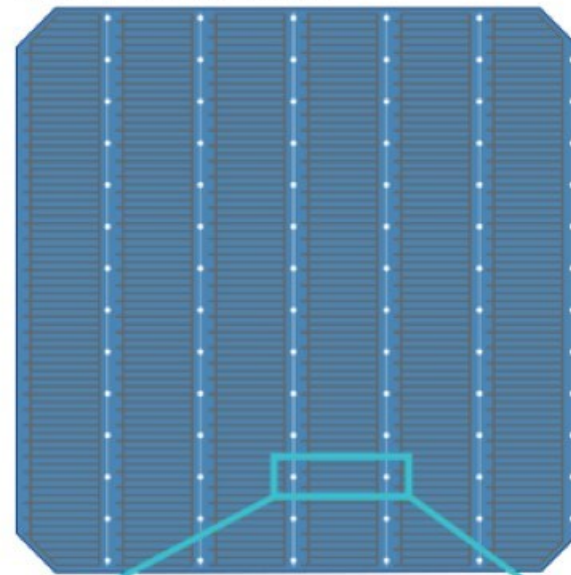
- No handling of individual sub cells

Front Metallisation



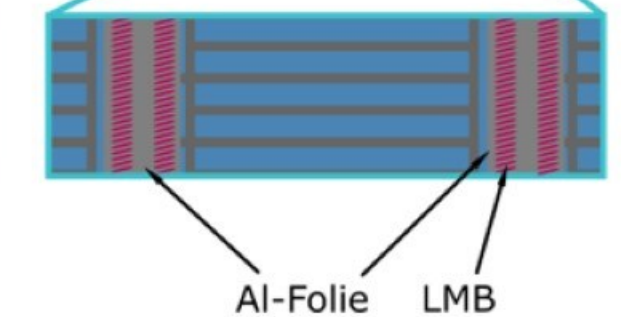
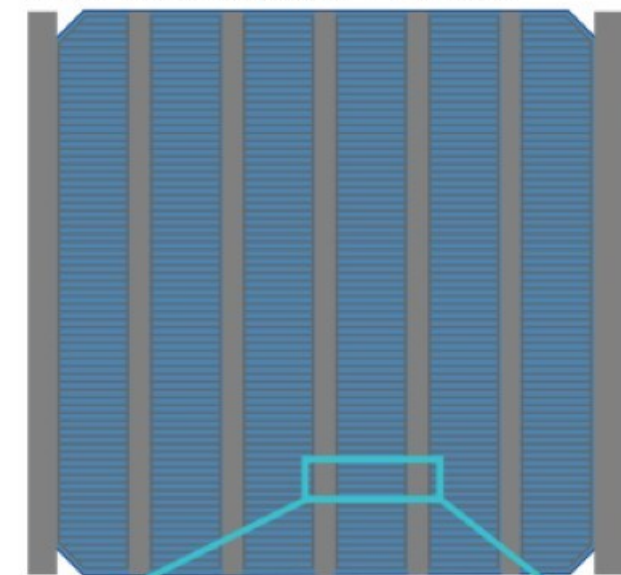
Busbar Ag-Finger Via

Rear Metallisation



Al-Finger Ag-Finger Via

Rear Metallisation + Al-Foil



Al-Folie LMB

FoilMet meets MWT – High Voltages by Simplified Series Interconnection

Reduced Handling

Front

- Finger
- Busbar
- Via

Rear

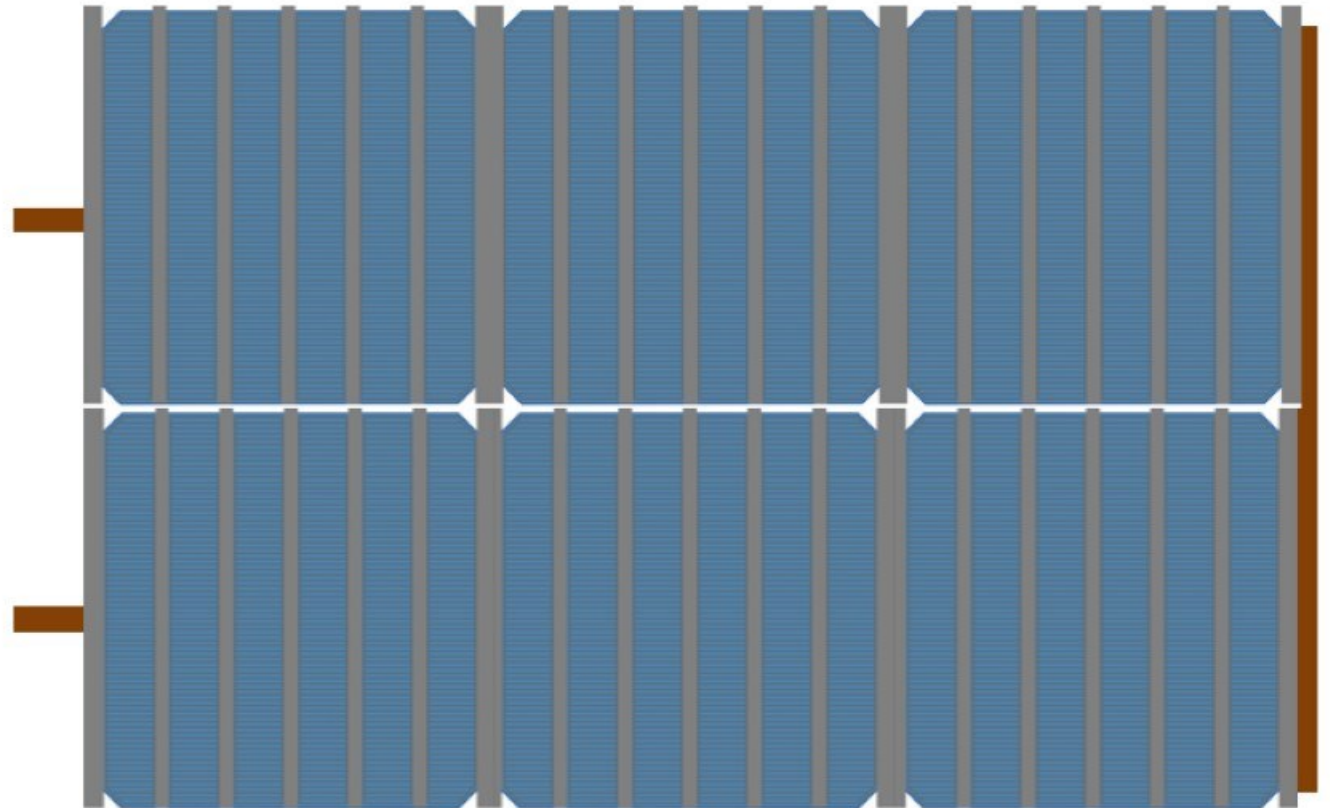
- Finger
- Via

Al-Folie

- LMB on p-electrode
- LMB on n-electrode
- Cut foil

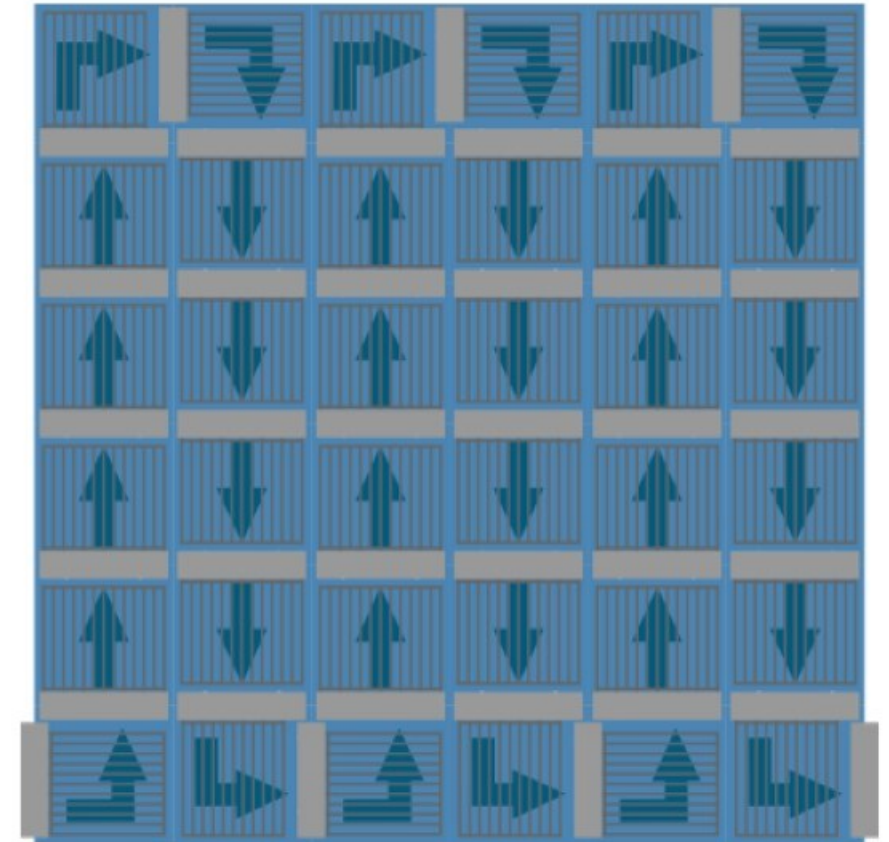
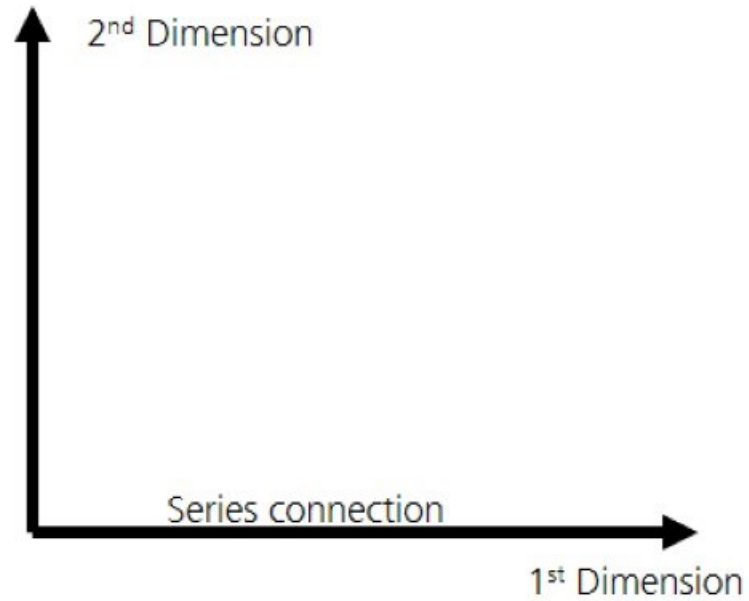
TLS cell

- No handling of individual subcells
- Laser multiple cells at once
- Including terminals



FoilMet meets MWT – High Voltages by Simplified Series Interconnection

Maximizing Voltage by Adjusted Cell Design



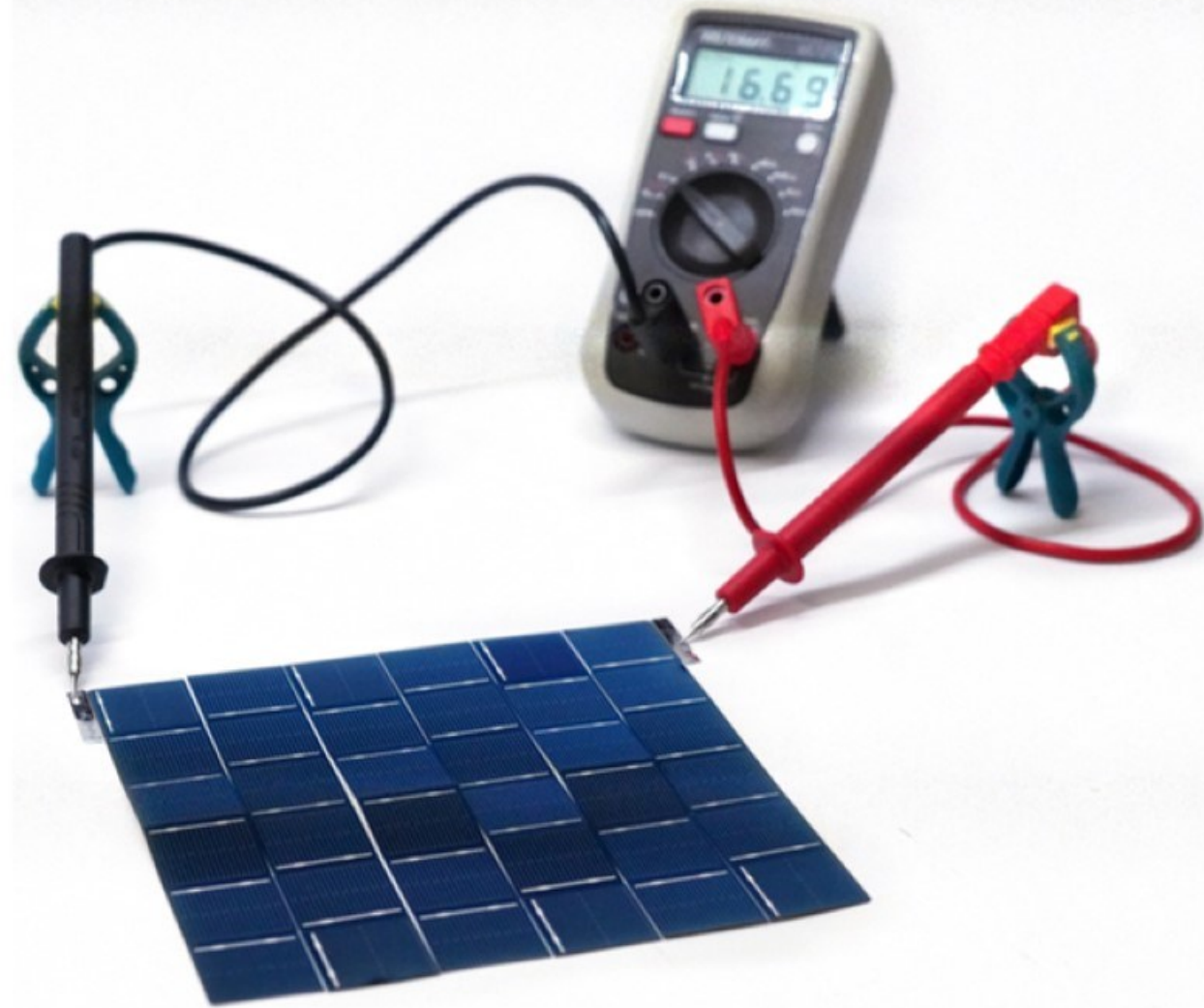
FoilMet „HV Prototype“

Proof-of-Principle

I-V Measurement

Id	I_{SC}/mA	V_{OC}/V	I_{MPP}/mA	V_{MPP}/V	FF/%	P_{MPP}/W	$\eta/\%$
1	273.7	24.41	233.0	19.69	68.7	4.59	17.90
2	274.4	24.37	235.2	19.72	69.4	4.64	18.02

- **High Voltage from a single wafer**
 - No Handling of small sub cells: Interconnect first, then separate
→ Handling only at host cell level
- **Cost efficient**
 - Reduction of the handling workload, interconnector materials and (manual) pick and place
- **Flexible Foil and Cell Matrix**
 - Can be integrated into custom shaped modules, e.g. curved modules





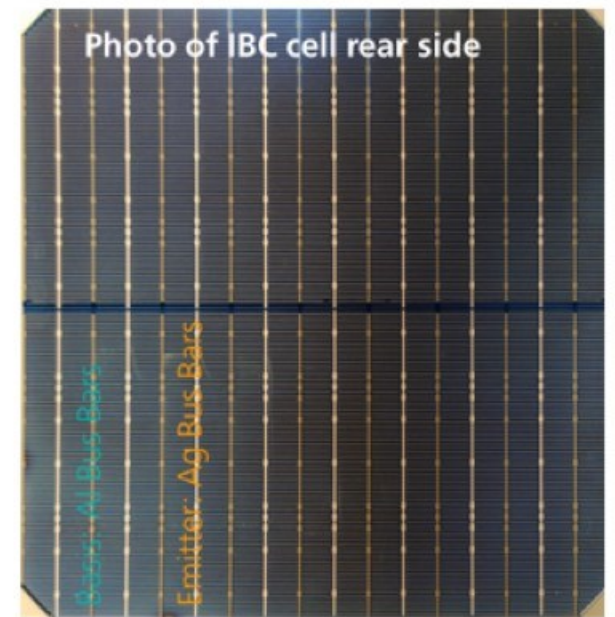
FoilMet meets SPINAT

POPEI and SPINAT: p-IBC meets Foilmet

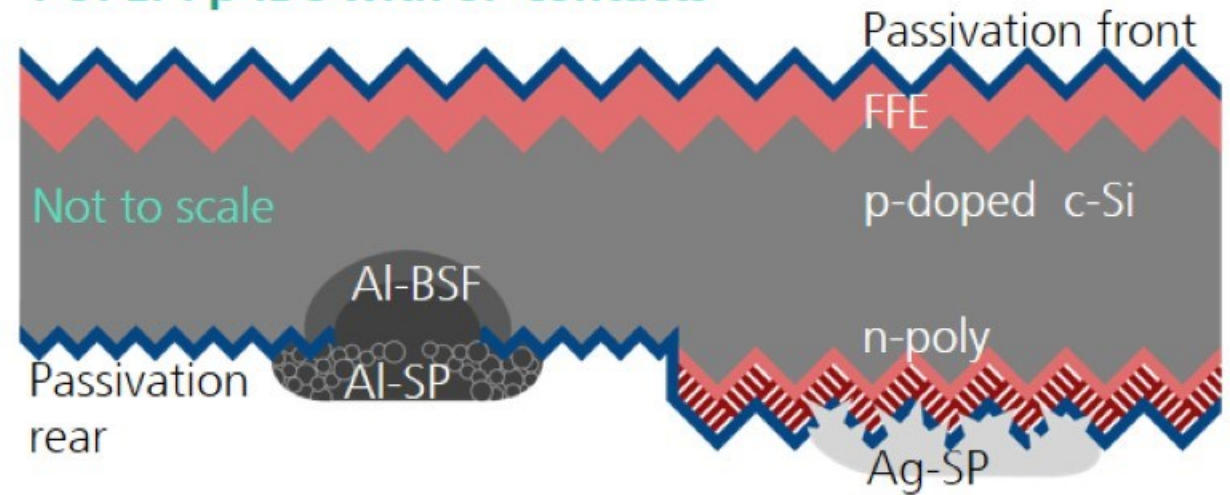
POPEI¹: Screen printed p-IBC

p-IBC cell:
screen printed Ag & Al contacts

- p-doped Cz-silicon
- Aluminum for base contact (PERC contact)
- Silver fingers for contact to n-poly-Si (TOPCon emitter contact)



POPEI¹: p-IBC with SP contacts

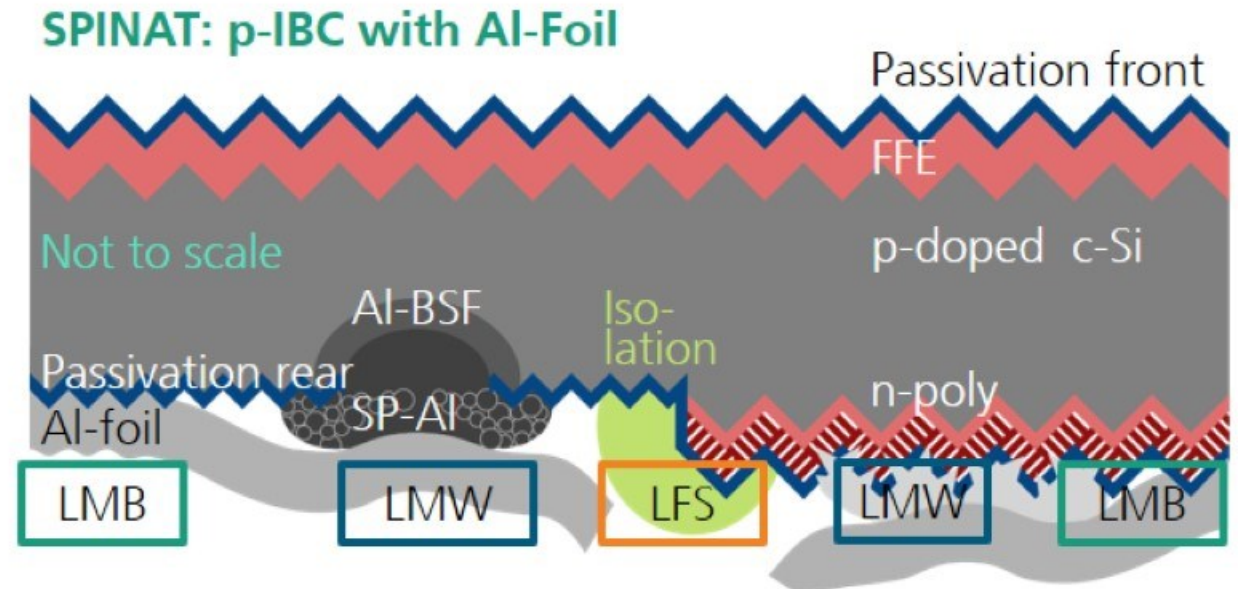


POPEI and SPINAT: p-IBC meets Foilmet

SPINAT¹: Foilmet Interconnection for Al and Ag contacts + bonds for adhesion (+ foil cutting)

Required laser processes - overview

- **LMB**: Laser-Metal-Bonding
adhere foil damage free to passivation layer
- **LMW**: Laser-Metal-Welding (Al-foil to Al-SP)
connect foil with screen printed Al paste
- **LMW**: Laser-Metal-Welding (Al-foil to Ag-SP)
connect foil with screen printed Ag paste
- **LFS**: Laser-Foil-Separation (separate sheet)
electrically isolate p- and n-regions

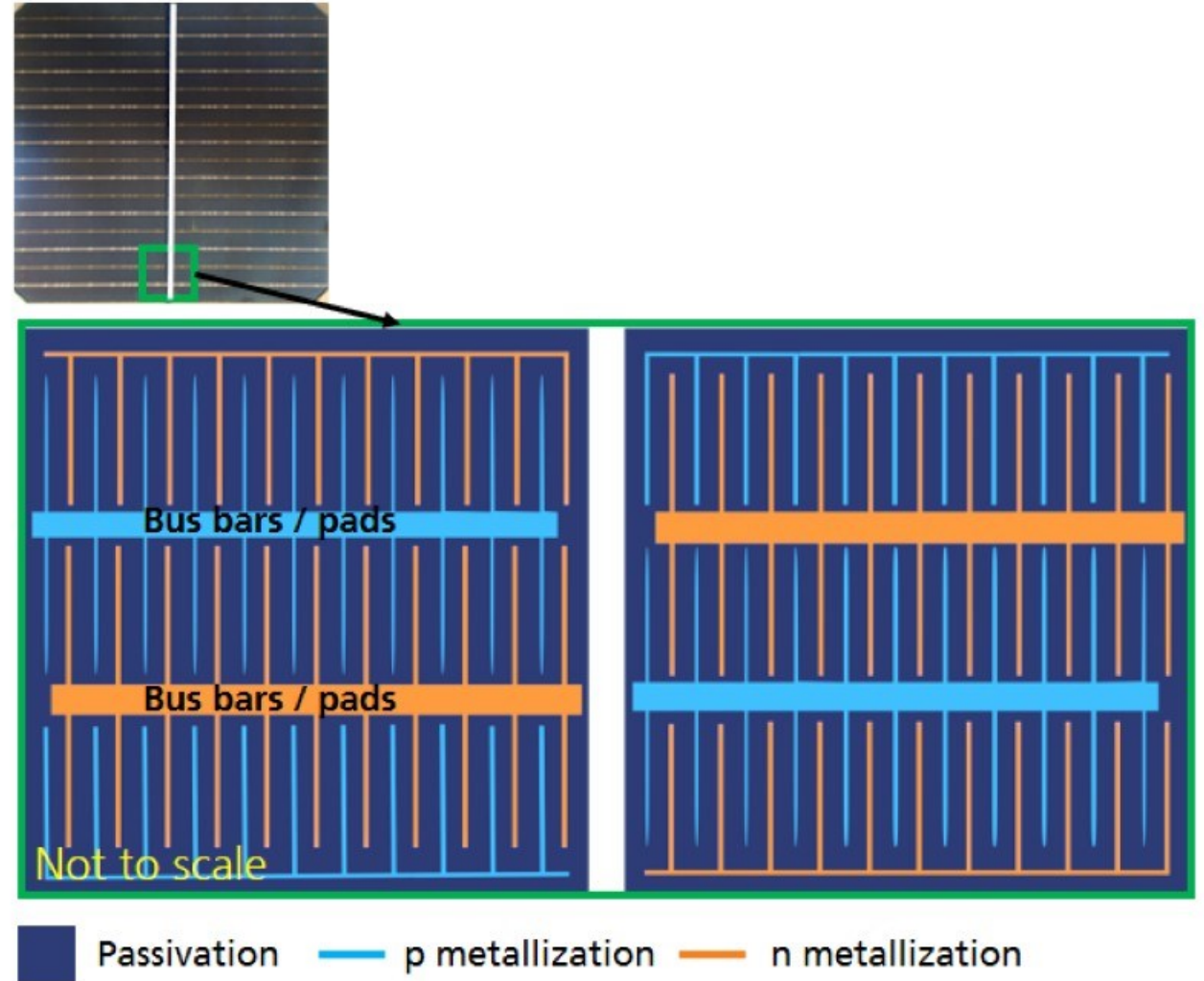


POPEI and SPINAT: p-IBC meets Foilmet

Interconnection Concepts by Al foil

Use one sheet of Al-foil for cell connection & interconnection of cells

- From fully screen printed contacts to FoilMet®

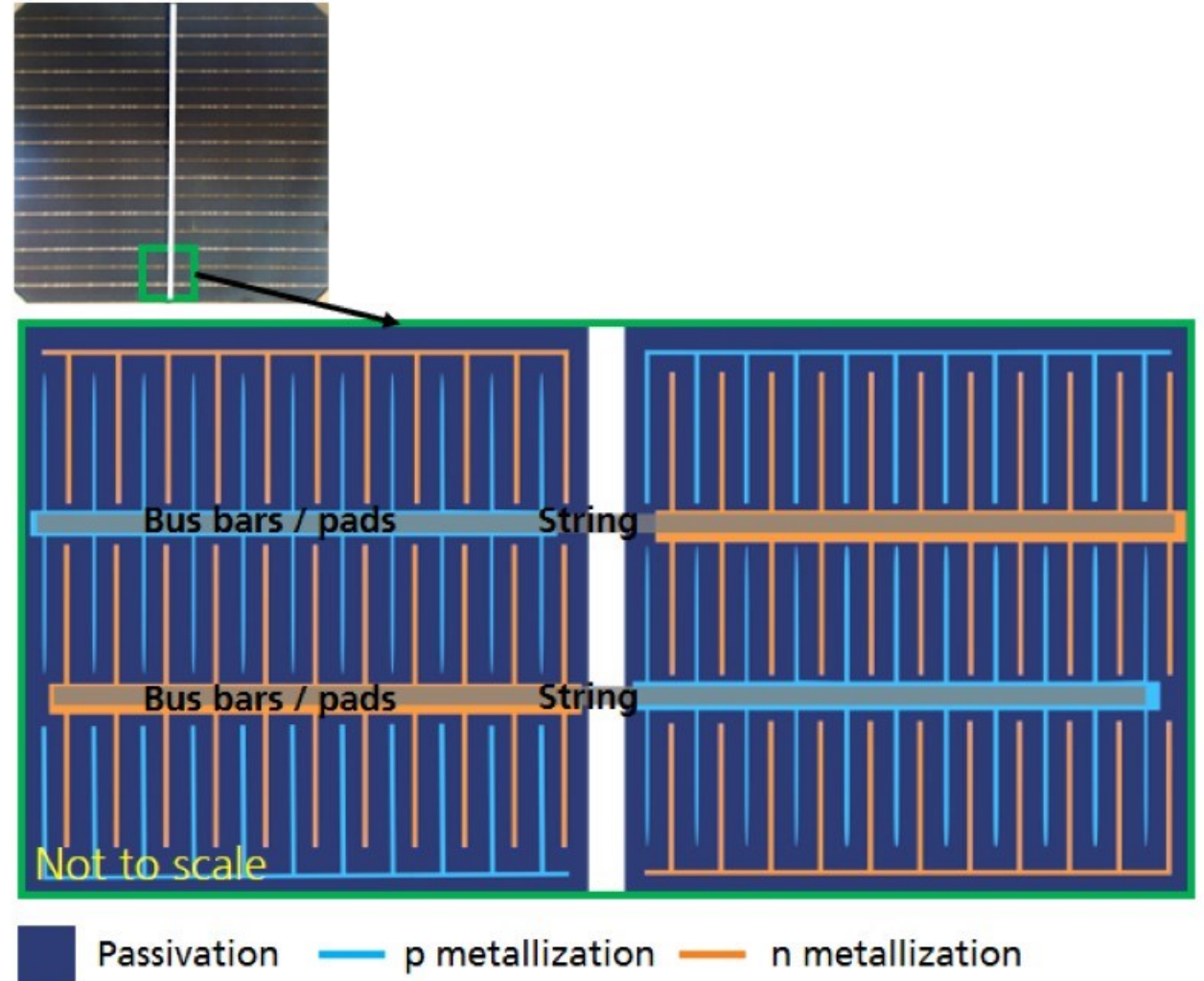


POPEI and SPINAT: p-IBC meets Foilmet

Interconnection Concepts by Al foil

Use one sheet of Al-foil for cell connection & interconnection of cells

- From fully screen printed contacts to FoilMet®
- Including interconnection of cells

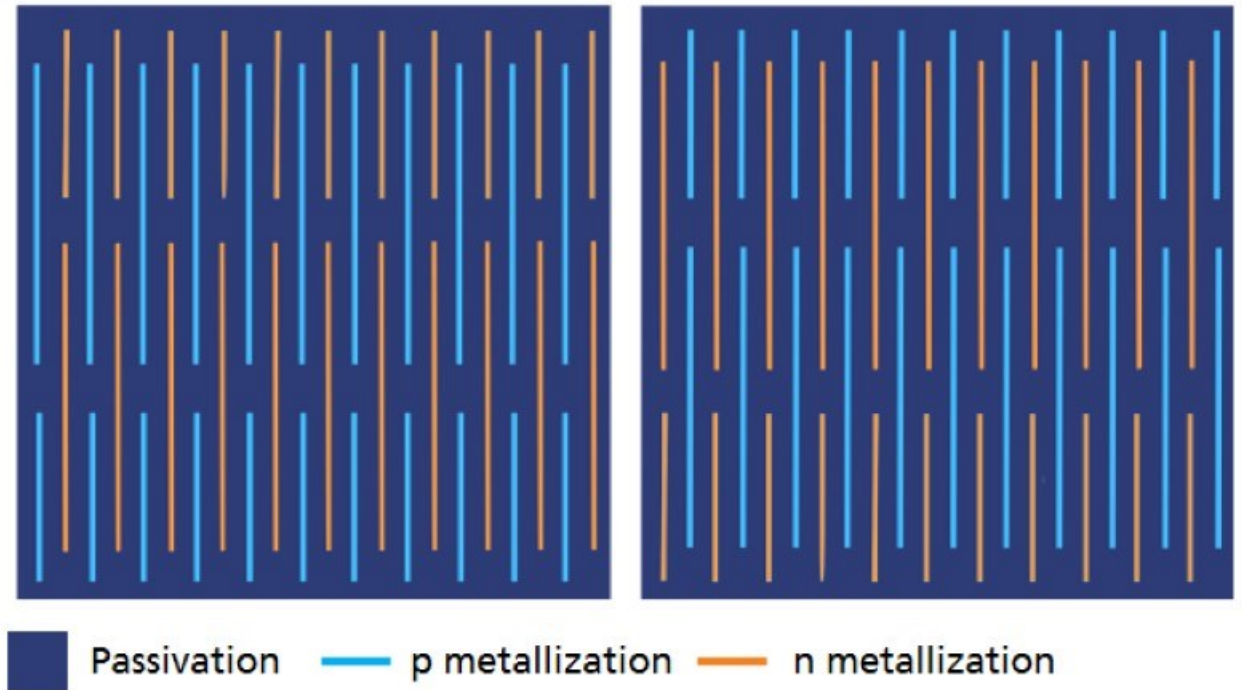


POPEI and SPINAT: p-IBC meets Foilmet

Interconnection Concepts by Al foil

Use one sheet of Al-foil for cell connection & interconnection of cells

- From fully screen printed contacts to FoilMet®
- Including interconnection of cells
- Leaving out bus bars, redundant lines, pads



Proof of Concept for Foil Metallization on (p-IBC) Cell Structure

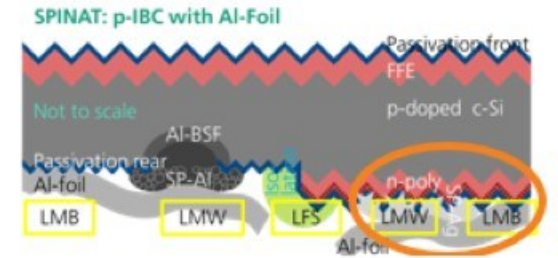
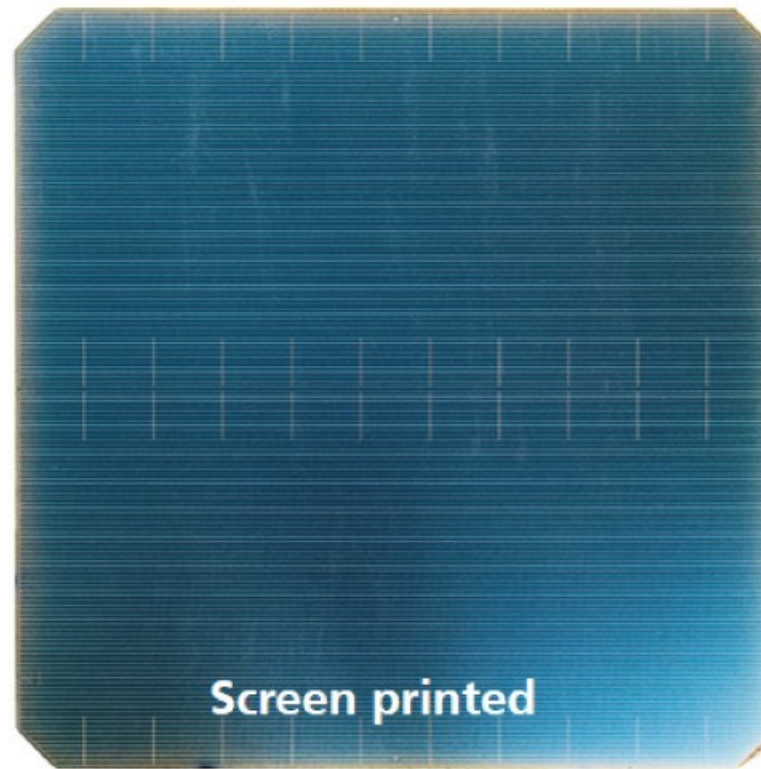
LMB / LMW on TOPCoRE solar cells

Proof-of-concept

- Front-and-rear contacted TOPCoRE cell (p-Si wafer, front surface field, rear TOPCon emitter)
- Screen printed vs. FoilMet emitter contacts

Photo:

Rear side TOPCoRe cells:
Screen printed / FoilMet

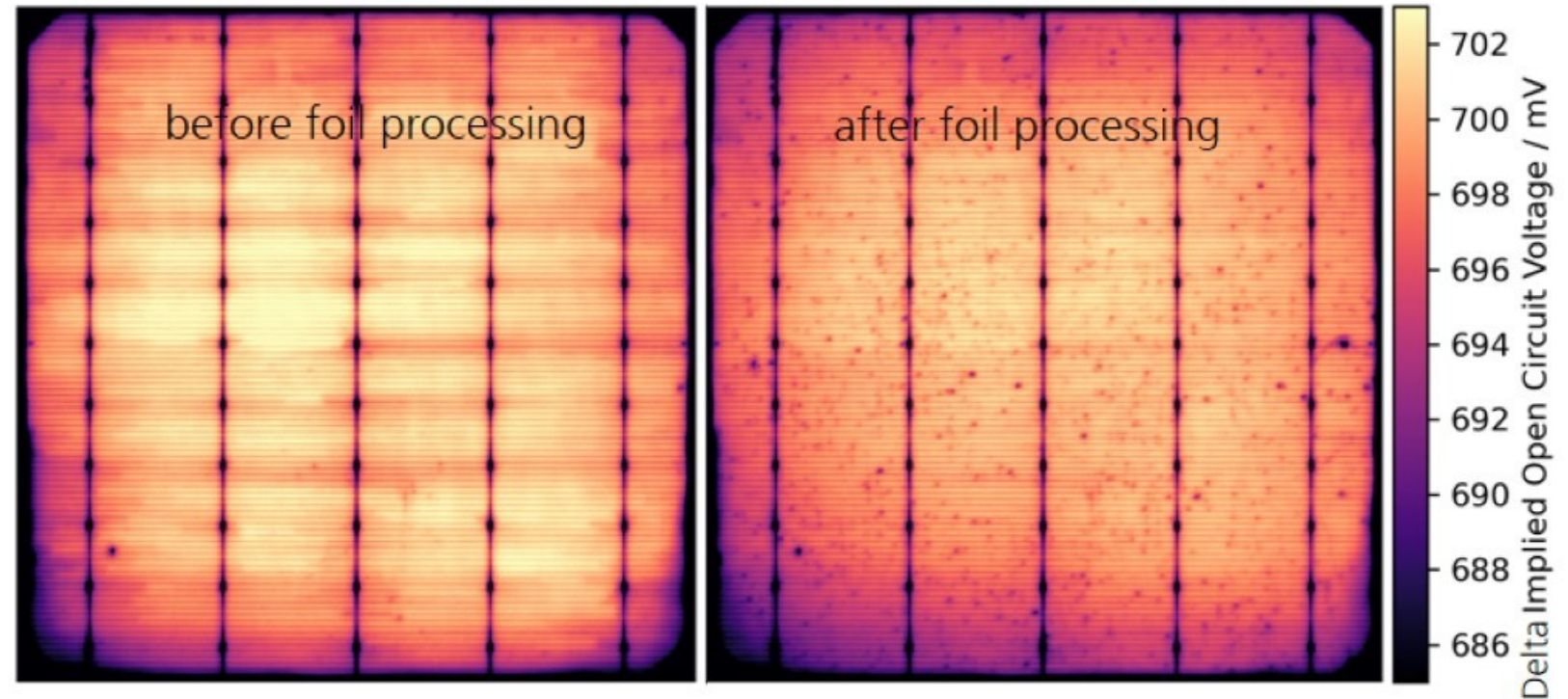
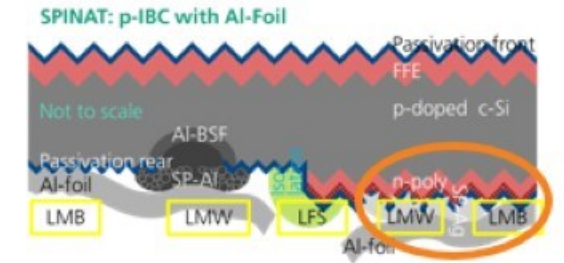


Proof of Concept for Foil Metallization on (p-IBC) Cell Structure

LMB / LMW on TOPCoRE solar cells

Results

- Peel tests for adhesion successful
 - Analysis of iV_{oc} (ΔiV_{oc} images) loss of ~ 1.3 mV (± 1.1 mV)
- **Low impact LMB / LMW process**
- I - V Measurements performed on the best solar cell



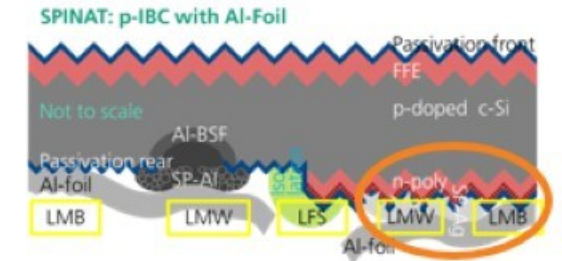
Proof of Concept for Foil Metallization on p-IBC Cell Structure

LMW of Ag contacts on TOPCoRE solar cells

Results

- Demonstration of screen printed and FoilMet® metallized TOPCoRE solar cells
- *I-V* parameter equal to the screen printed reference (low level due to precursor issues)

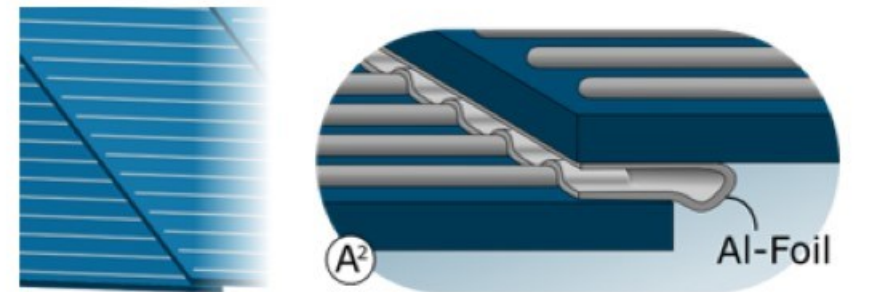
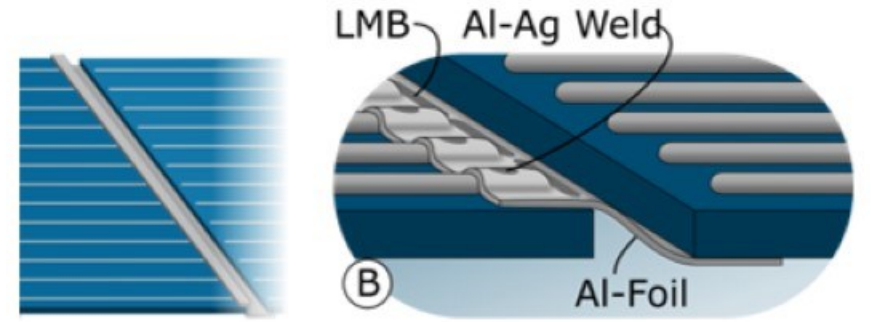
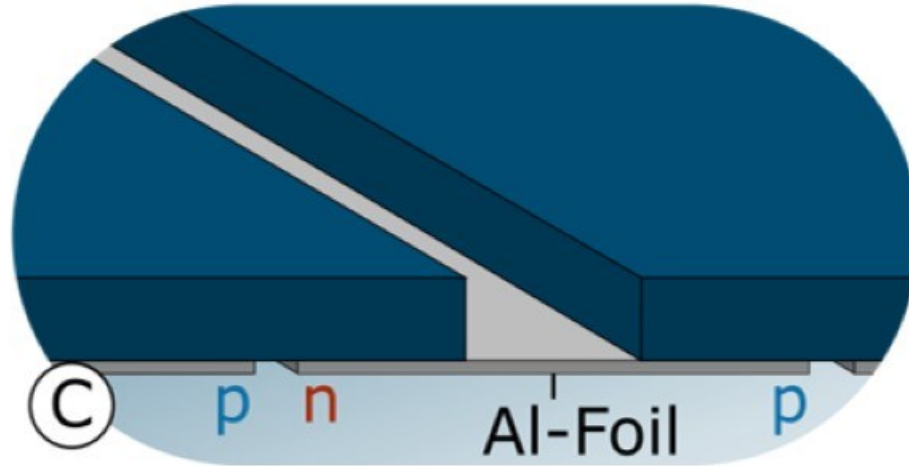
→ **Proof of successful combination of LMB and LMW on TOPCoRE solar cells**



	V_{oc}	J_{sc}	η	FF
	(mV)	(mA/cm ²)	(%)	(%)
Screen printed reference	698.8	39.0	21.5	79.1
Foil metallized cell	701.2	39.0	21.5	78.5

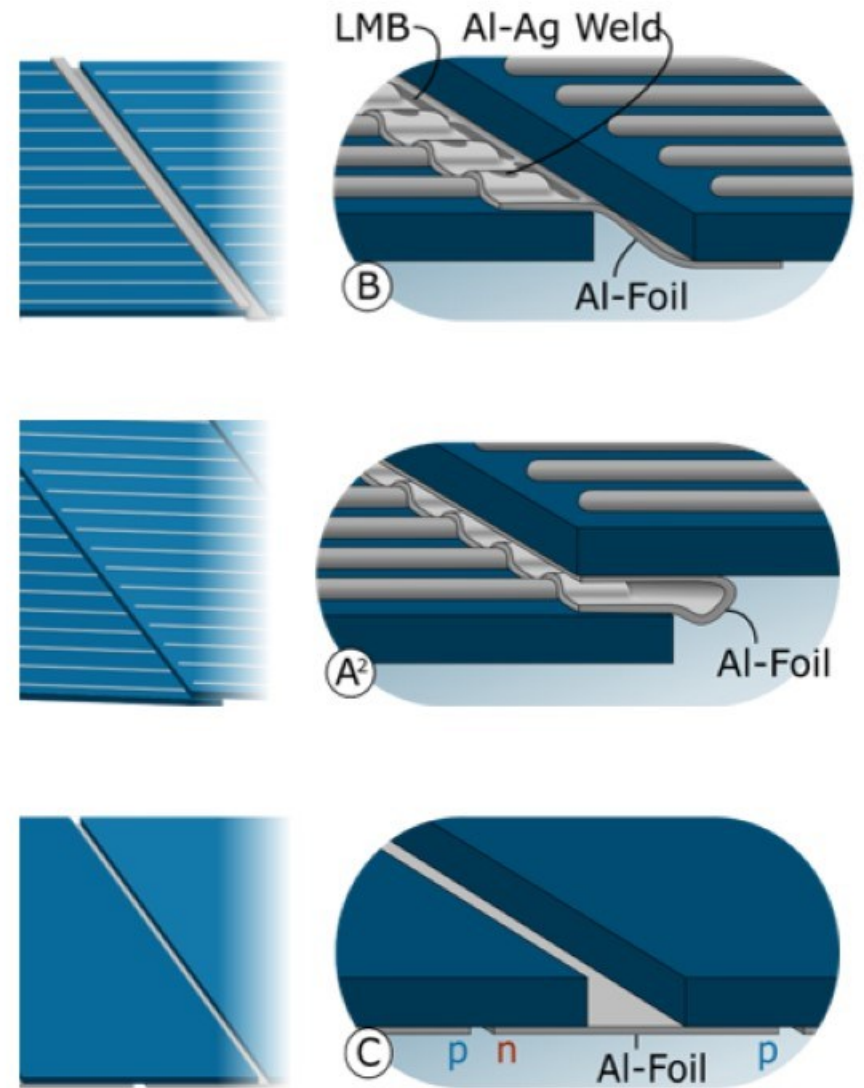
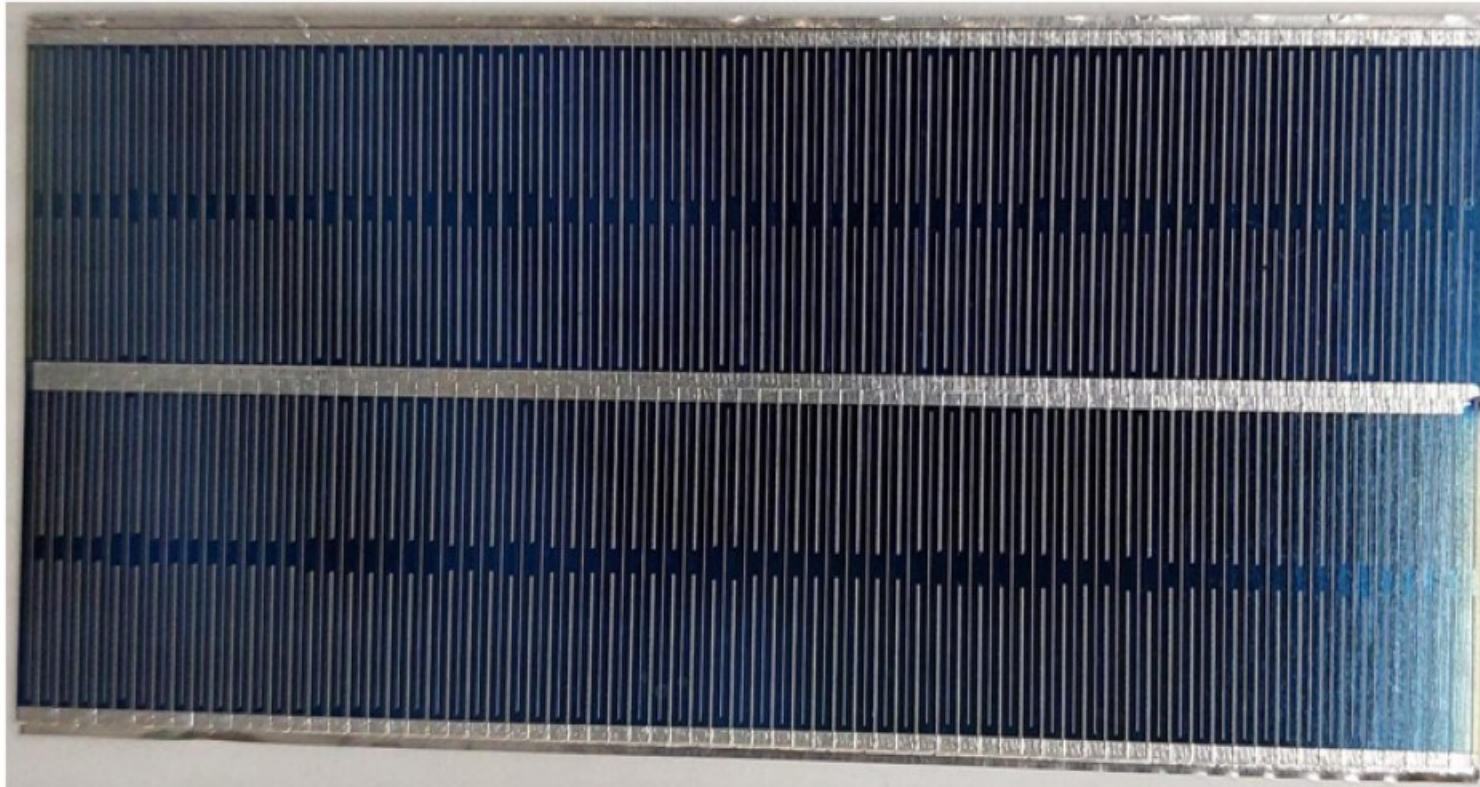
"FOILMET[®]-Interconnect" for IBC

One-sided Edge Interconnection for Cell Stripes



"FOILMET[®]-Interconnect" for IBC

Proof-of-Concept



Summary and Outlook

Flexible Cell Interconnection Using Al-Foils and Laser Processing

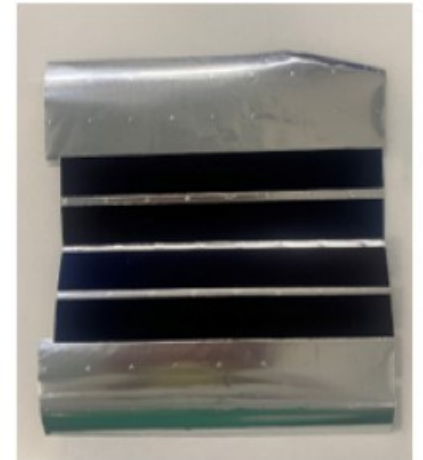
FoilMet-Interconnection

- Utilizing Al-foil to eliminate costly materials (e.g. Cu-ribbons)
- Good electrical performance, strong mechanical adhesion by adjusted processes
 - Weld Al to Al, Ag for electric contacts or bond Al to surfaces for adhesion
- Reduce Ag consumption, by eliminating the need for busbars
 - Reliable interconnection on each finger

FoilMet meets Back-Contact

- Single sided interconnection allows new cell designs (e.g. high voltages)
 - 24 V from a single wafer
- Replace ribbons by Al-foil or go for edge interconnection
- Less handling / higher throughput by interconnection first, cutting second

Interested? Feel free to reach out for samplings, customization or collaborations!



Thank you
for your attention!

Dr. Jonas D. Huyeng
Metallization and Structuring Technologies
Photovoltaics
jonas.huyeng@ise.fraunhofer.de

Many thanks to:

all co-workers and industry partners.

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by the German Bundestag**